



“Increased radiation tolerance of CMOS sensors with small collection electrodes through accelerated charge collection”

a.k.a.

“first results from the MiniMALTA demonstrator”

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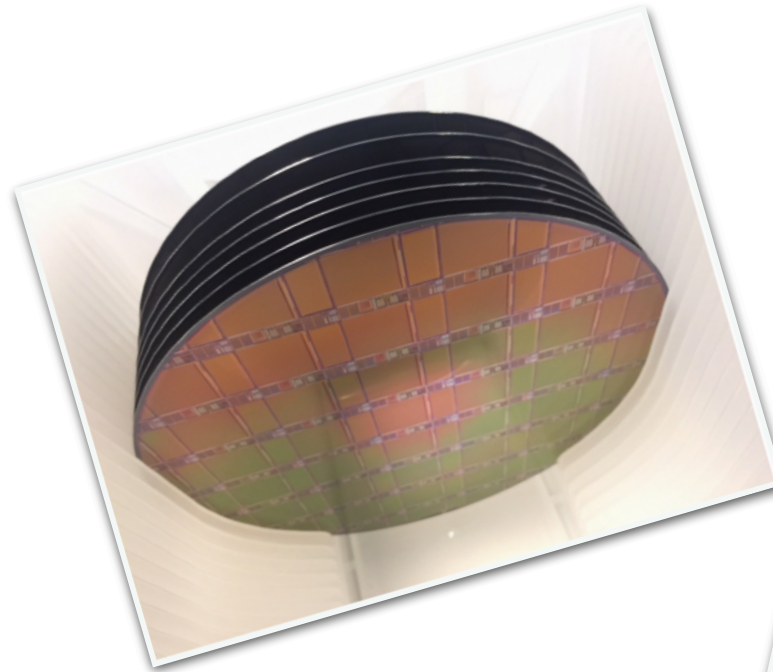
Valerio Dao

CERN

TWEPP2019, Santiago de Compostela

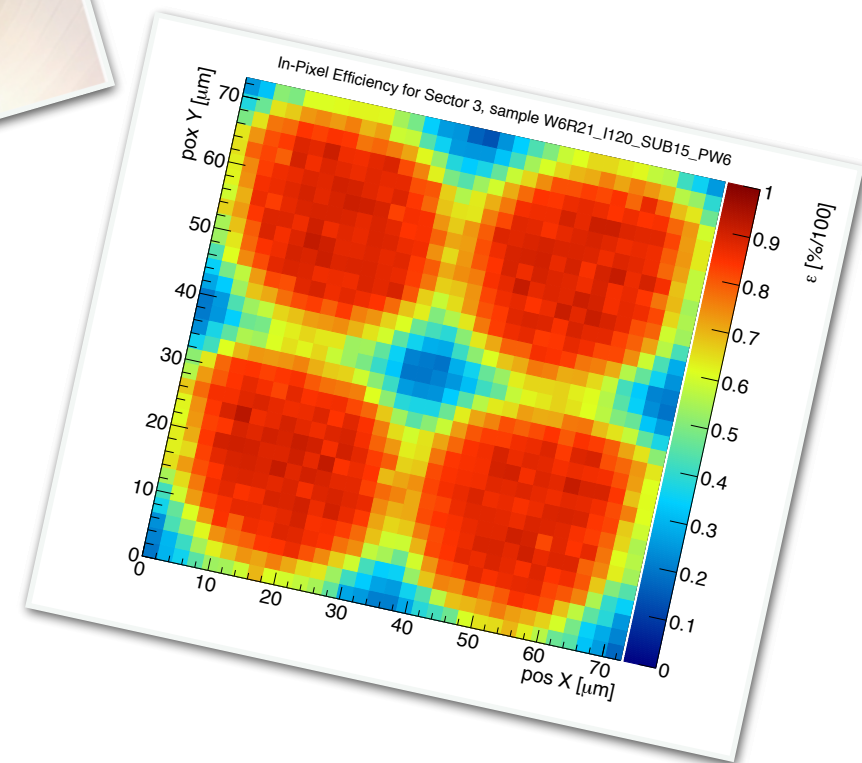
03-09-2019

- ◆ CMOS detectors



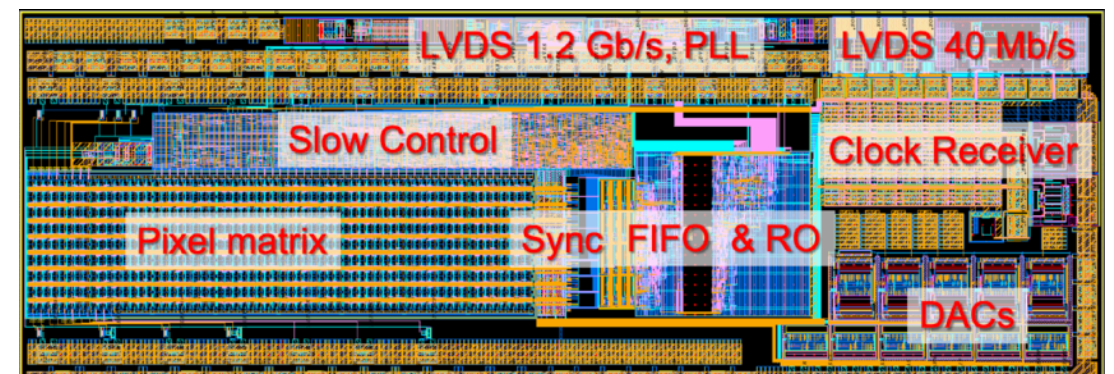
- ◆ a quick recap: *the MALTA chip*

- ◆ design
- ◆ results



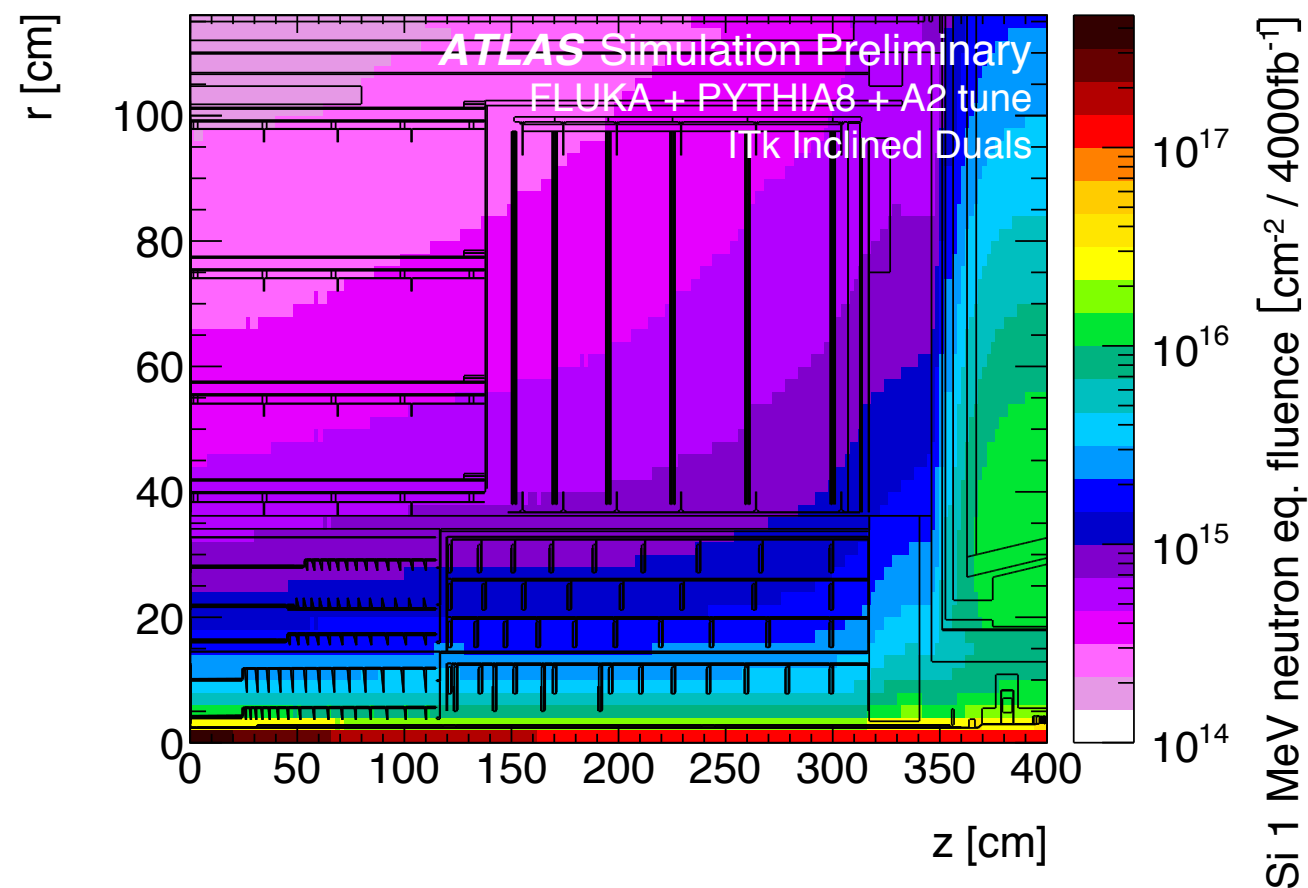
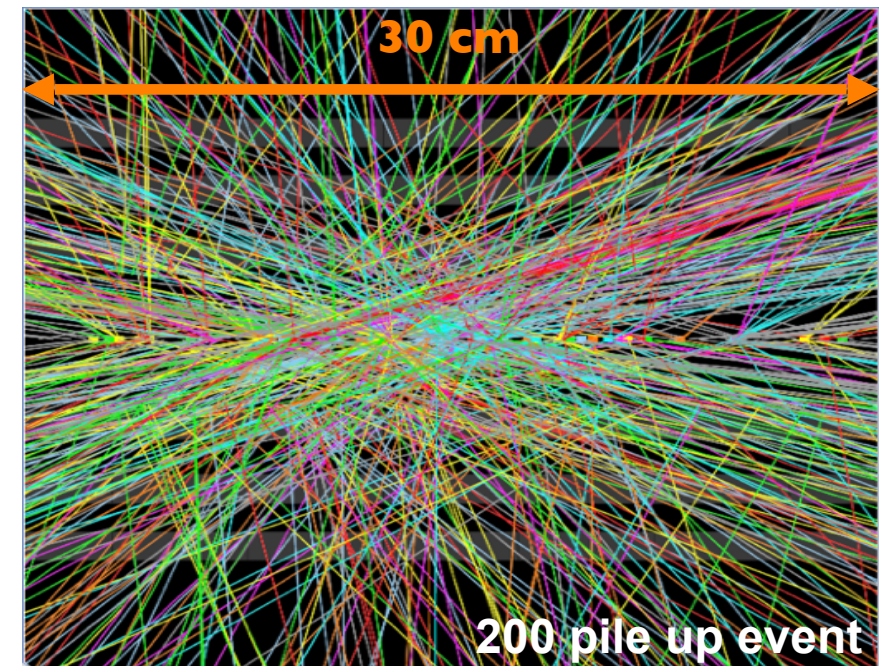
- ◆ learning from the results: *the Mini-MALTA prototype*

- ◆ design
- ◆ results

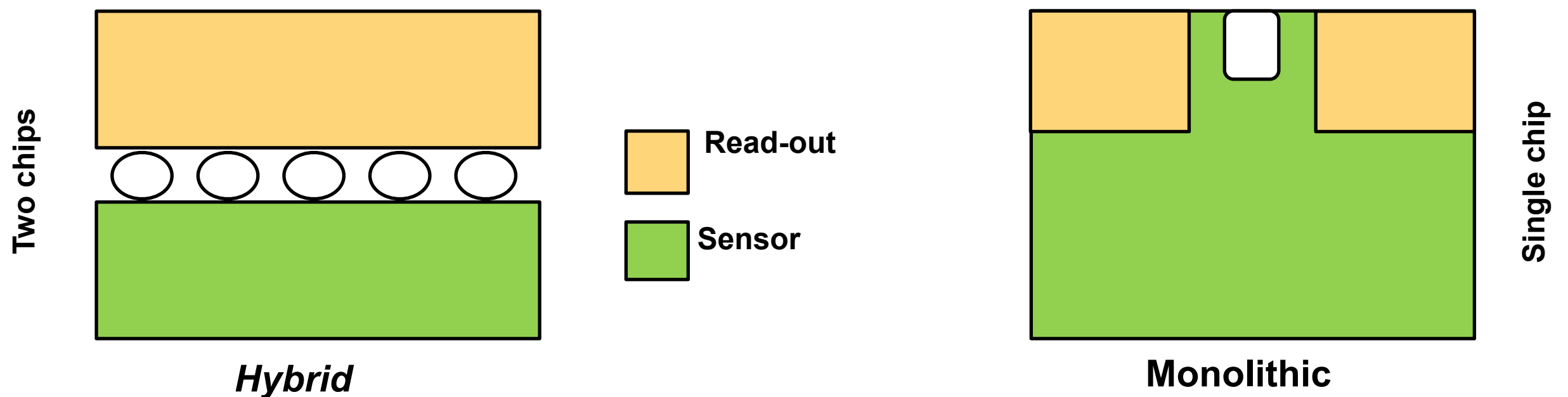


(one of) the next challenges for pixel detectors

- ◆ Upcoming colliders (HL-LHC, FCChh) will run at very high instantaneous luminosities:
 - ◆ 8-30 $10^{34} \text{ cm}^{-2}\text{s}^{-1}$
 - ◆ significant amount of pileup (200-1000) interactions per bunch crossing



- ◆ Large hit rate: 200 MHz/cm²
 - ◆ need small pixel to separate individual particles
- ◆ Very large radiation dose:
 - ◆ HL-LHC pixel detector: $2 \times 10^{16} - 1 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2 \text{ NIEL}$
 - ◆ current LHC detectors need to be replaced at the end of Run3



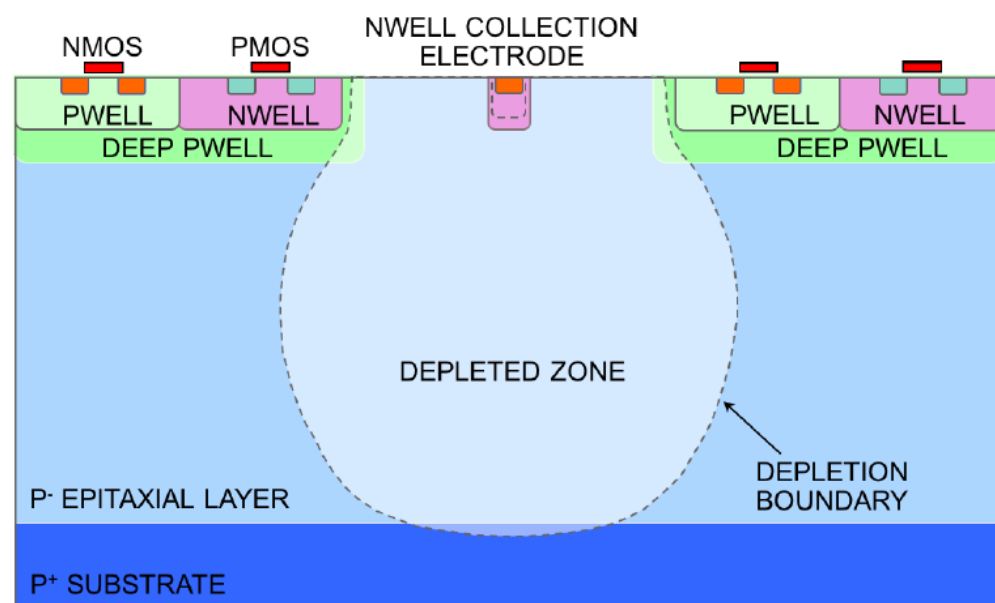
♦ Hybrid silicon detectors:

- ♦ most popular technology in current large scale detectors
- ♦ well known technology with proven radiation hard properties
- ♦ reasonably expensive and custom process

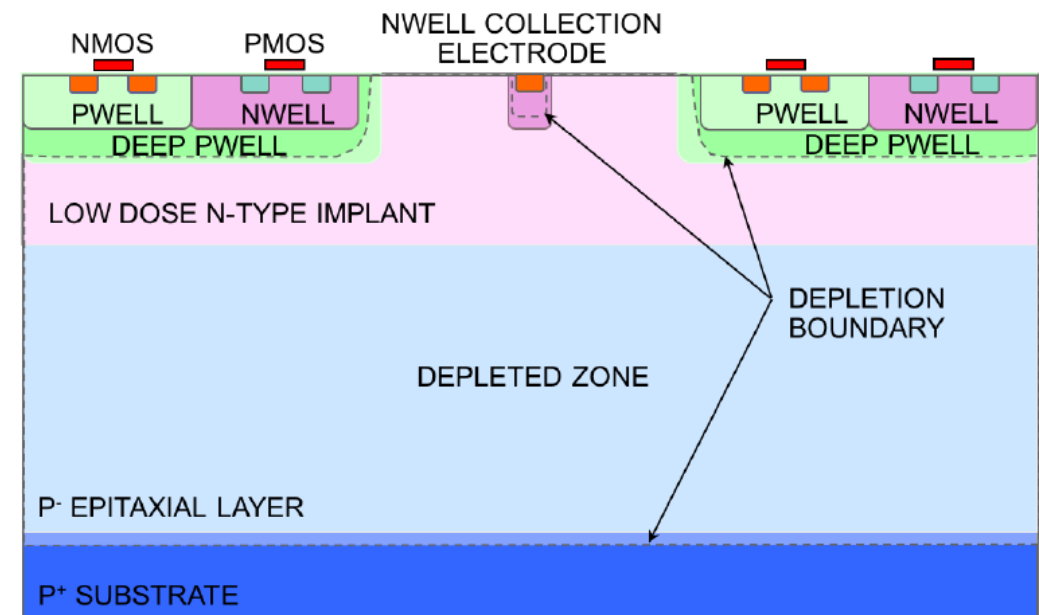
♦ Monolithic CMOS:

- ♦ industrial-like production: suited for large area detector
- ♦ small segmentation to maintain low occupancy in high particle flux
- ♦ potential for low material budget and low power detector
- ♦ still in R&D phase (in particular for what concern radiation hardness)

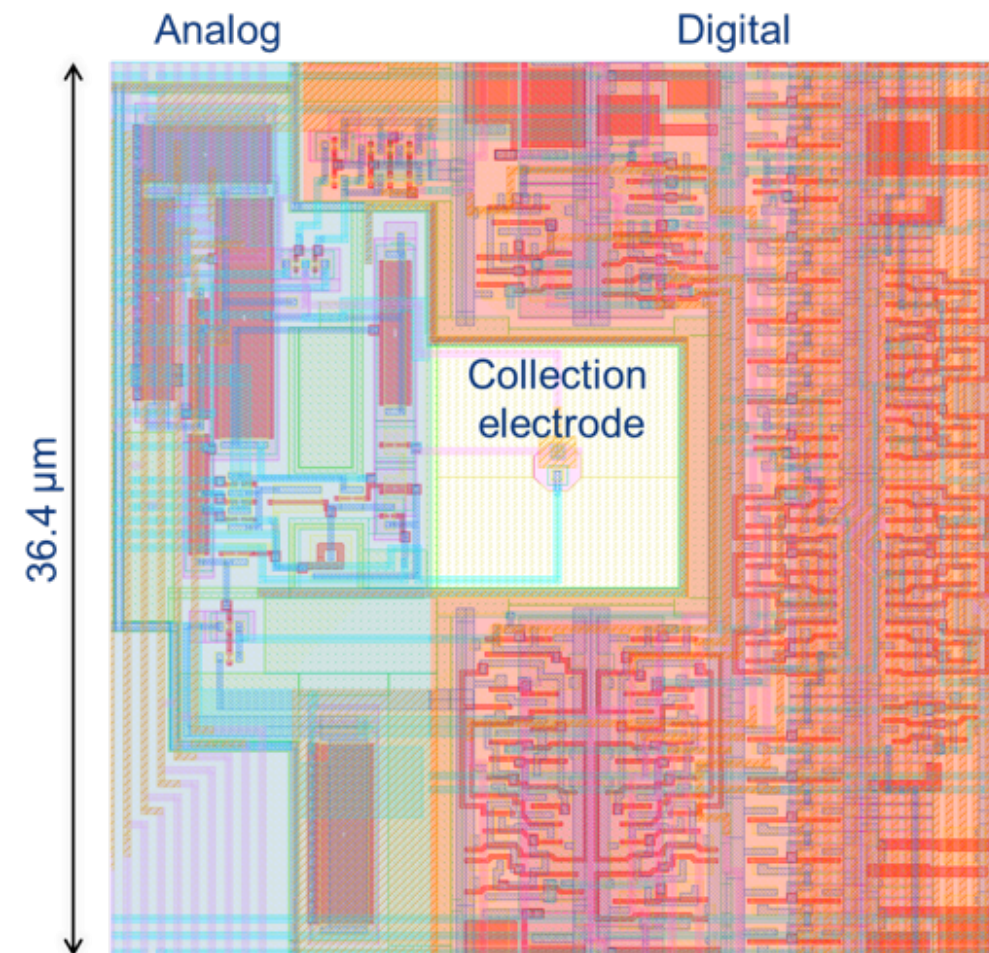
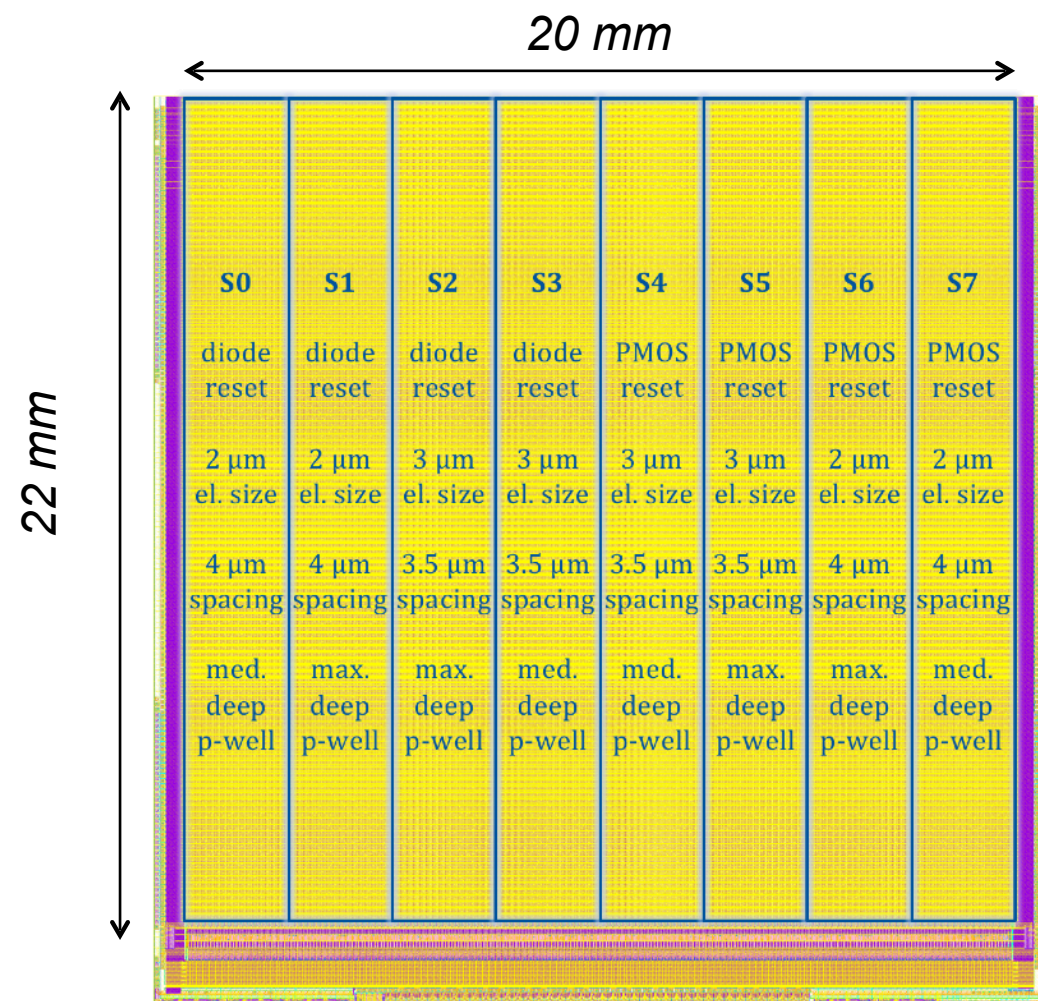
- ♦ Successfully implemented for the ALICE ITS
- ♦ Small collection electrode \rightarrow small input capacitance
- ♦ Small depletion depth: 25-30 μm
- ♦ modified process with additional low dose n-type implant:
 - ♦ achieve full lateral depletion
 - ♦ improve radiation hardness
- ♦ typical bias voltage: 6 - 20 V (substrate), 6V (pwell)



Standard Process

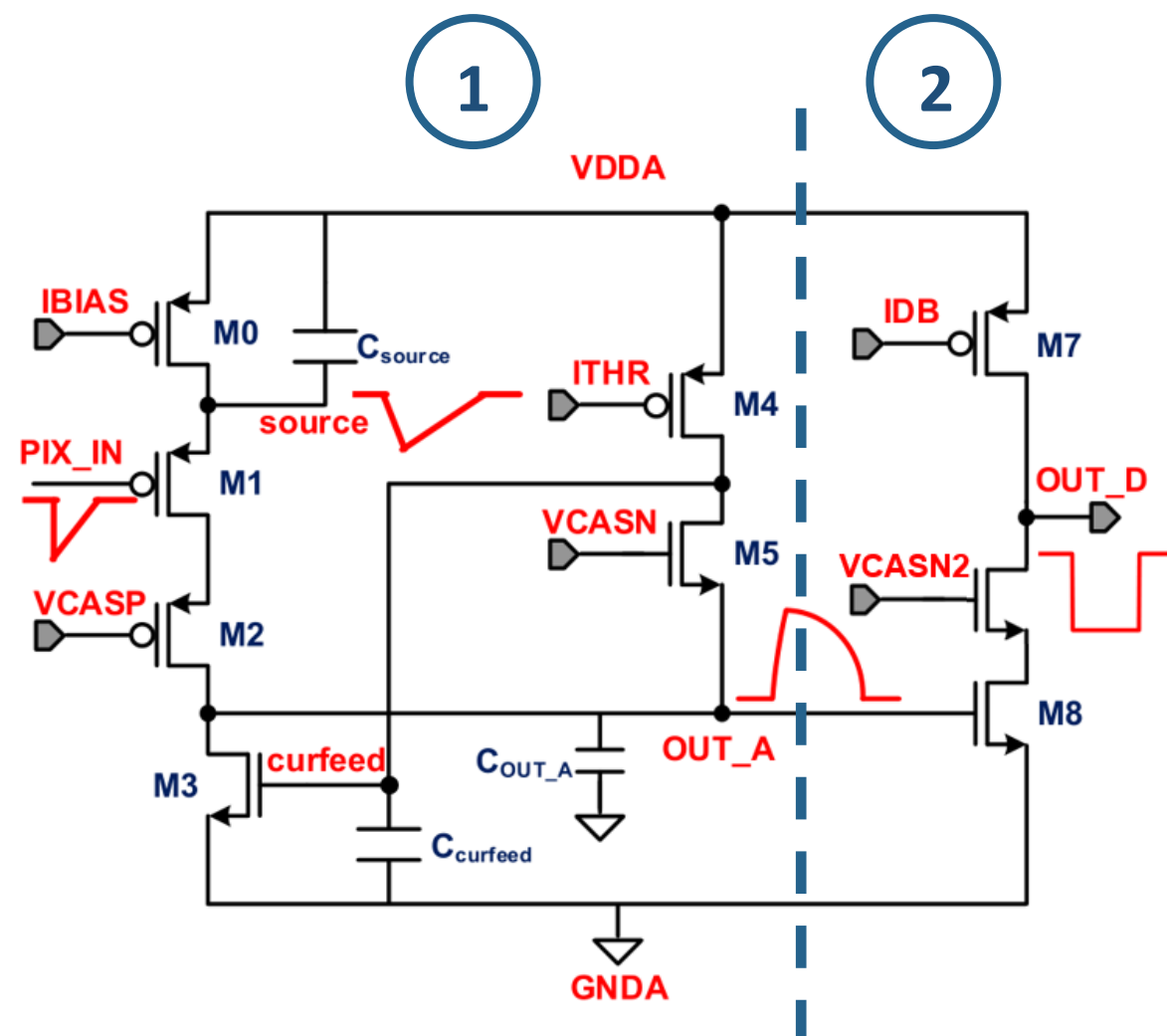


Modified Process



- ♦ 22 x 20 mm² full size demonstrator
- ♦ **512 x 512 pixels**
- ♦ 8 sectors with different pixel flavours
- ♦ **Fully clock-less matrix architecture**
- ♦ Charge information from time-walk
- ♦ 10 mW/cm² digital power

- ♦ Pixel size: 36.4 x 36.4 μm^2
- ♦ 2-3 μm^2 collection electrode:
 - ♦ **small input capacitance: few fF**
- ♦ 3.5-4 μm spacing to electronics:
 - ♦ **low cross talk**
- ♦ 1 μW /pixel analog power:
 - ♦ **70 mW/cm² digital power**

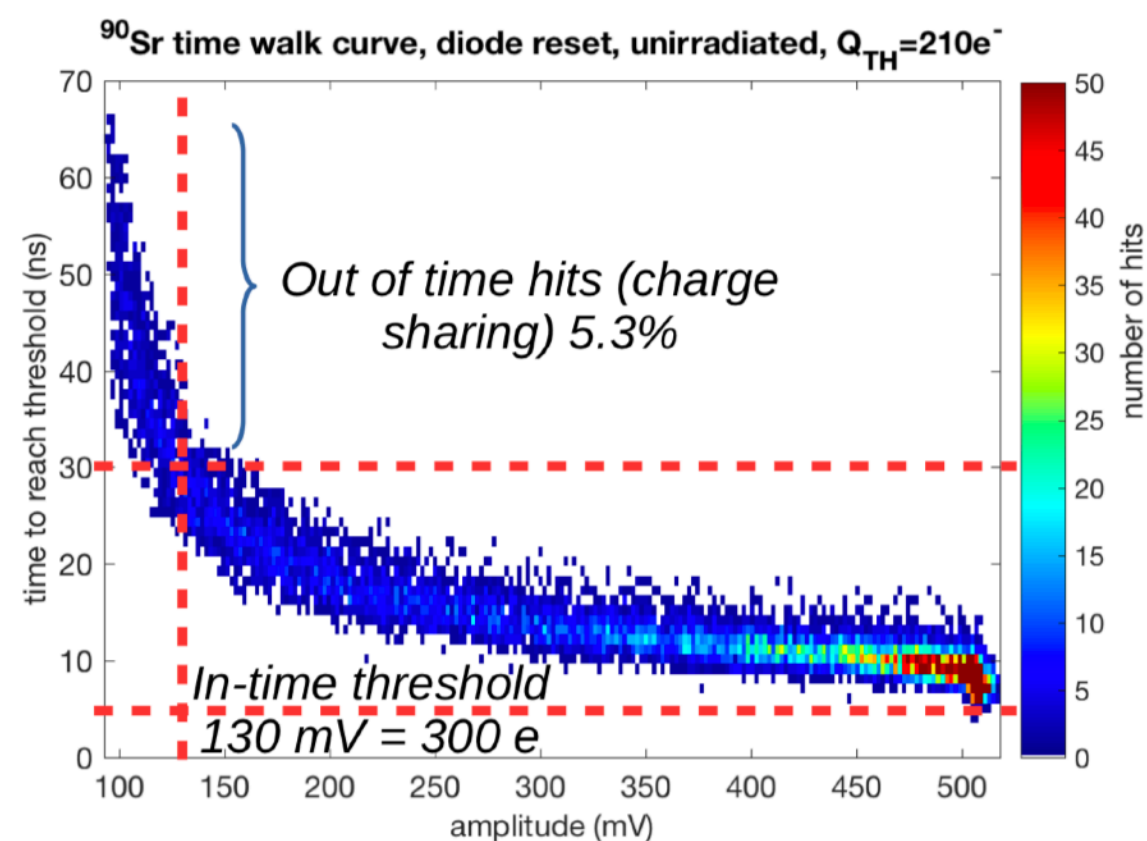


1 – amplification
2 – discrimination

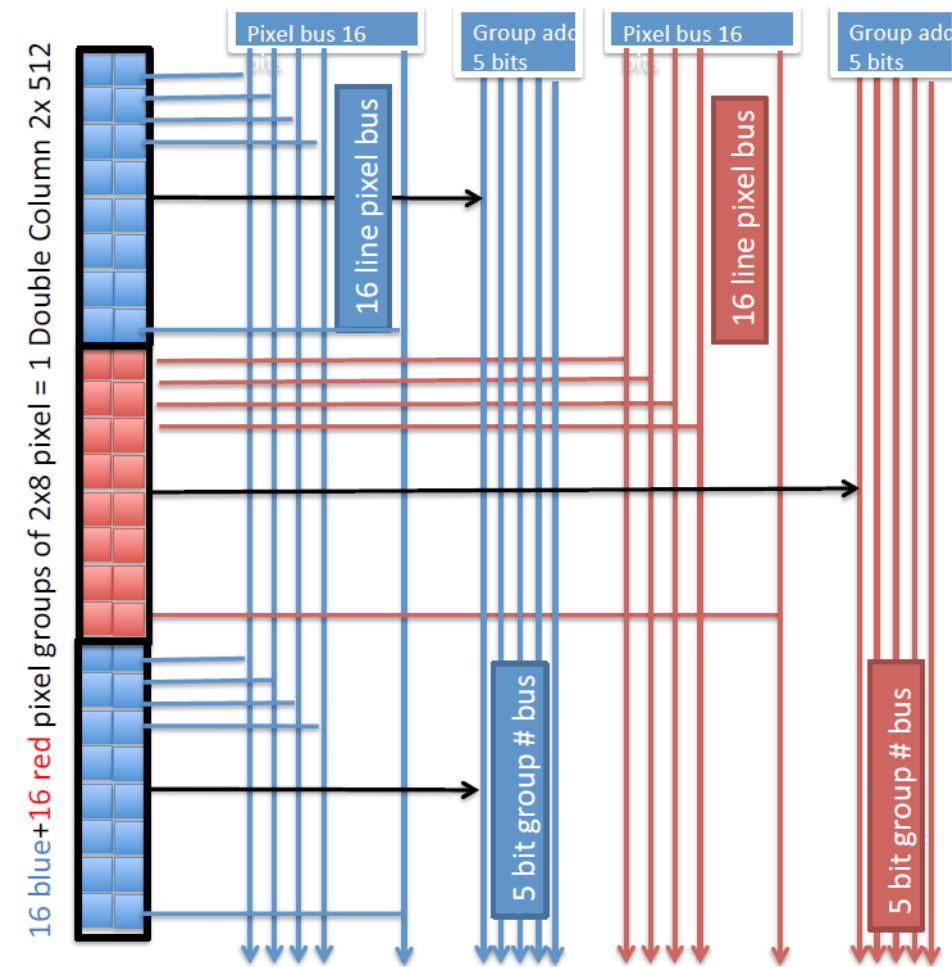
♦ Typical performance (before irradiation):

♦ $th \sim 250 \text{ el}$, $RMS \sim 35 \text{ el}$, $ENC \sim 7 \text{ el}$

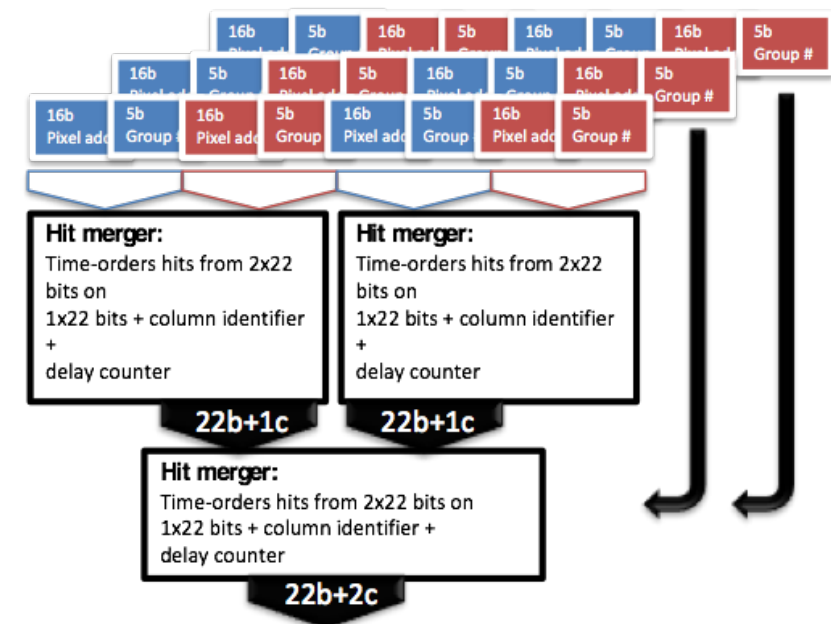
- ♦ Operating principle derived from ALPIDE front end
D. Kim et al. DOI 10.1088/1748-0221/11/02/C02042
- ♦ Charge measurement from time difference between bunch crossing time and leading edge of hit signal (no ToT)
- ♦ ***timewalk <25 ns for $Q > 300 \text{ el}$***



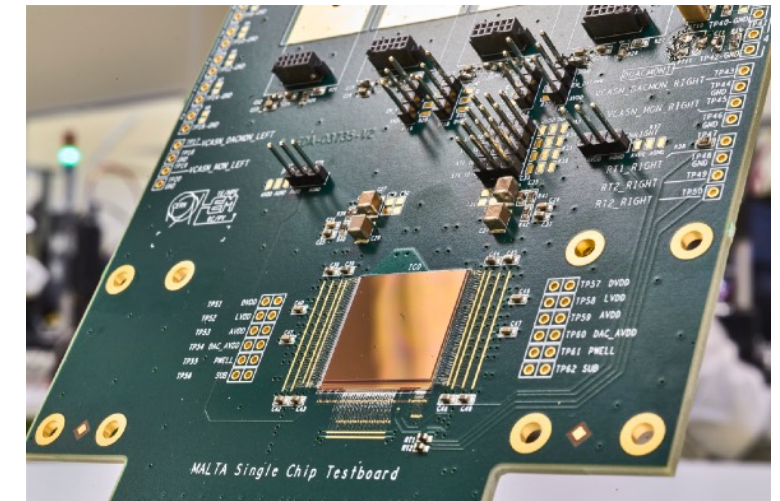
- ◆ Novel asynchronous readout architecture for high hit rate capability with 40 bit parallel data bus for data streaming:
 - ◆ Groups of 2x8 pixels with pattern assignment to reduce data size from clusters
 - ◆ Front-end discriminator output is processed by a double-column digital logic
 - ◆ Pulse width adjustable between 0.5 ns and 2 ns
 - ◆ Data transmitted asynchronously over high speed bus to end of column
- ◆ At the periphery, arbitration and merging resolves timing conflicts of simultaneous signals *[currently disabled]*:
 - ◆ Timing information stored in dedicated bits
 - ◆ Output signals transmitted by 5 Gbps LVDS driver
 - ◆ *one MALTA word consist of 38 bits*
- ◆ *Custom chip readout implemented in Virtex VC707:*
 - ◆ asynchronous oversample of parallel 38 lines
 - ◆ measuring hit arrival time with 400ps precision



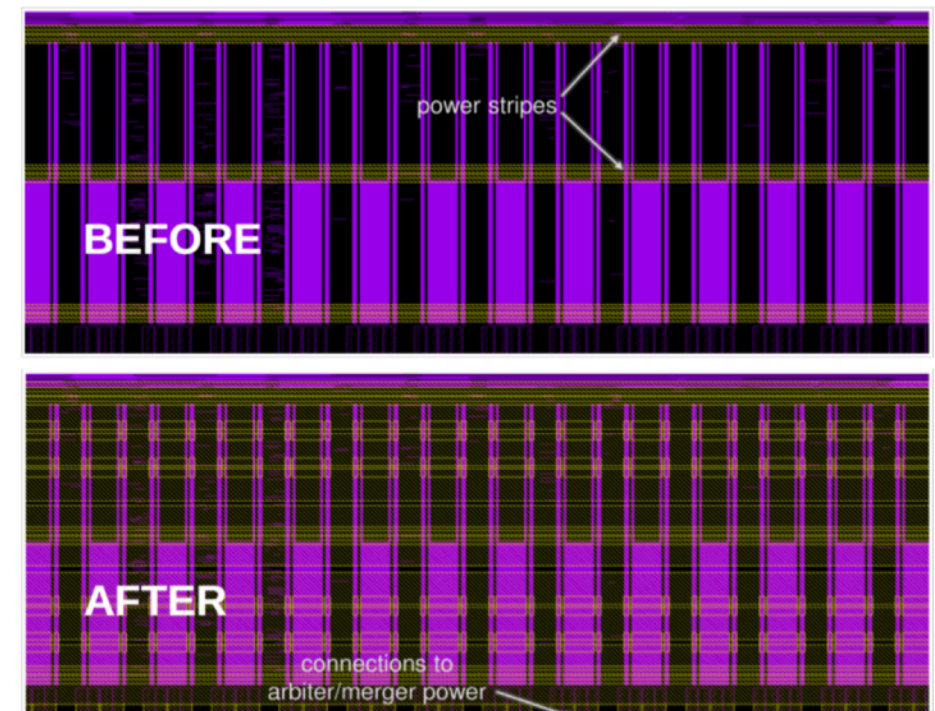
I Berdalovic et al. 2018 JINST 13 C01023



- ◆ **First submission [*]:** delivered in Jan 2018
 - ✦ pixel readout and pixel pulsing functional
 - ✦ slow control not fully functional → partial masking only on double column level, no individual pixels
 - ✦ hit merger in the periphery disabled due to too high noise activity can cause data collisions at very hit rate



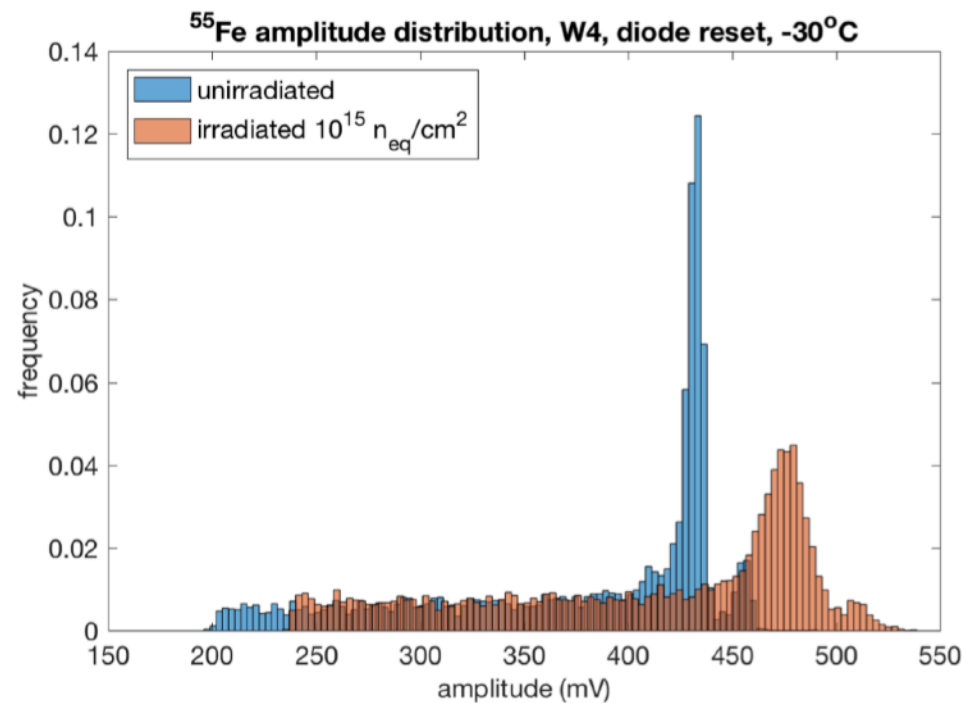
- ◆ **Second submission (MLVLC) [*]** delivered in Jun 2018
 - ✦ MLVLC = Metal Last Vias Last Change
 - ✦ Improve connections to digital power in the slow control block
 - ✦ Improve PWELL connections in the matrix
 - ✦ Chip behavior remained similar to first submission



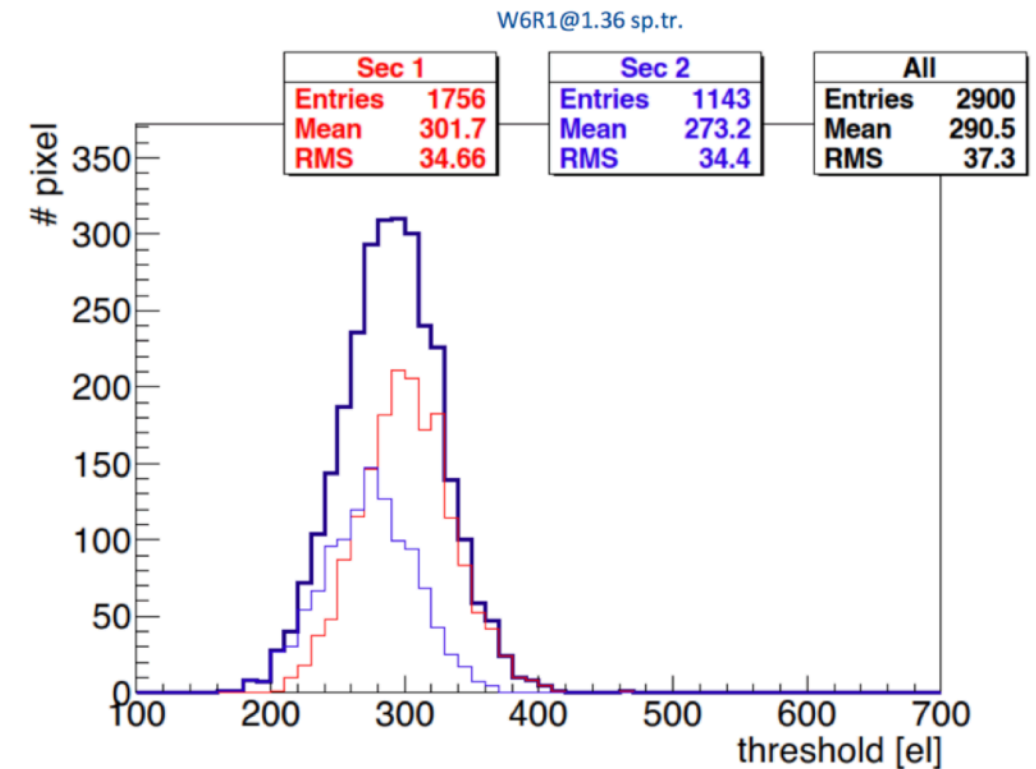
- ◆ **Third submission (MALTAC):** delivered in Febr 2019
 - ✦ fully functional Slow Control capabilities at reduced digital voltage

[*] chips irradiated up to $1e15 \text{ n}_{eq}/\text{cm}^2$

Analog signal properties

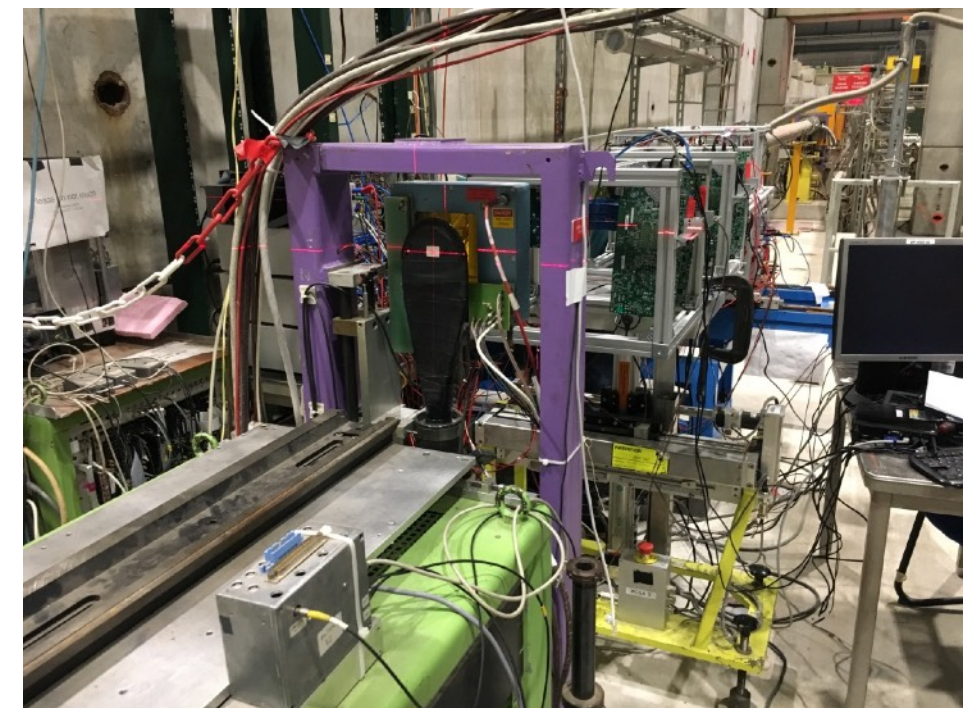


Threshold scan measurements



♦ Test beam campaigns at SPS:

- ♦ April-October 2018
- ♦ MIMOSA-based telescope: 2 μm resolution
- ♦ both unirradiated and samples irradiated up to $1e15 n_{eq}/cm^2$
- ♦ preliminary results presented last year by B. Hiti
- ♦ a quick recap in the next slides



Test beam results

high threshold:

- ✦ inefficiency for low signals (charge sharing)
- ✦ low noise

low threshold:

- ✦ higher sensitivity for low signal
- ✦ significantly larger noise
- ✦ lack of pixel masking produce inefficiency due to hit merging

Unirradiated
(W6R6,)

93.6 % — 97.1 % — 96.2 %

Decreasing threshold, from $\sim 600 e^-$ to $\sim 250(\text{unirr})/350(\text{irr}) e^-$

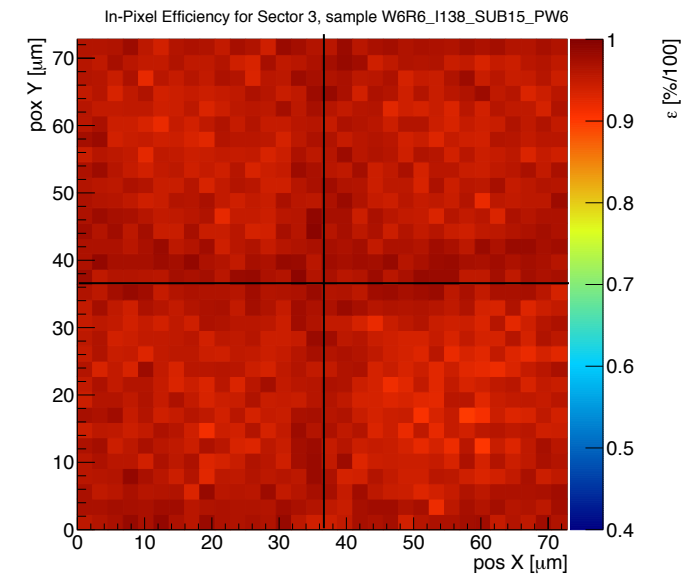
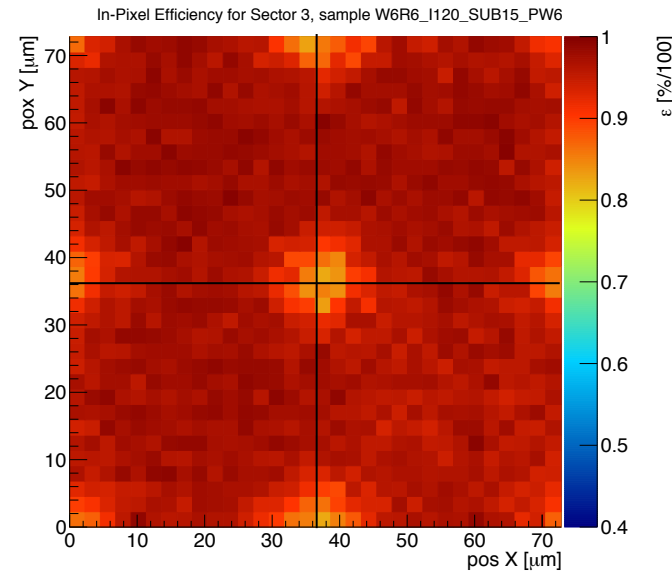
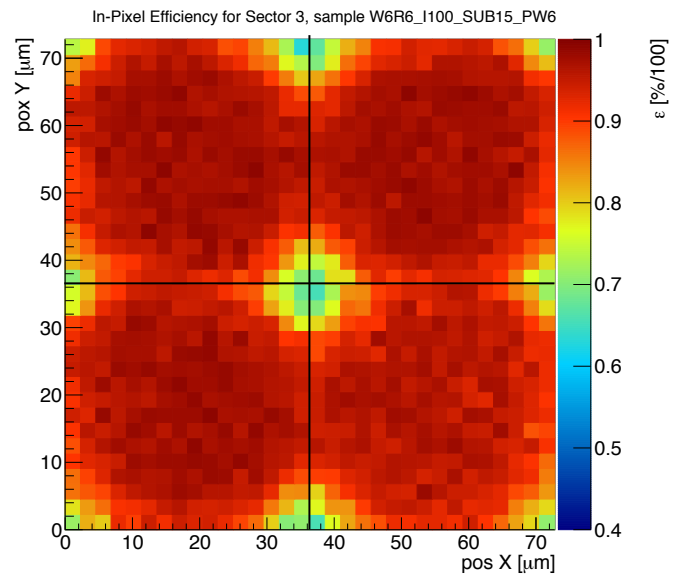
Irradiated
 $5 \times 10^{14} n_{\text{eq}}/\text{cm}^2$
(W6R21,)

55.1 % — 71.1 % —

Clear inefficiency seen after irradiation

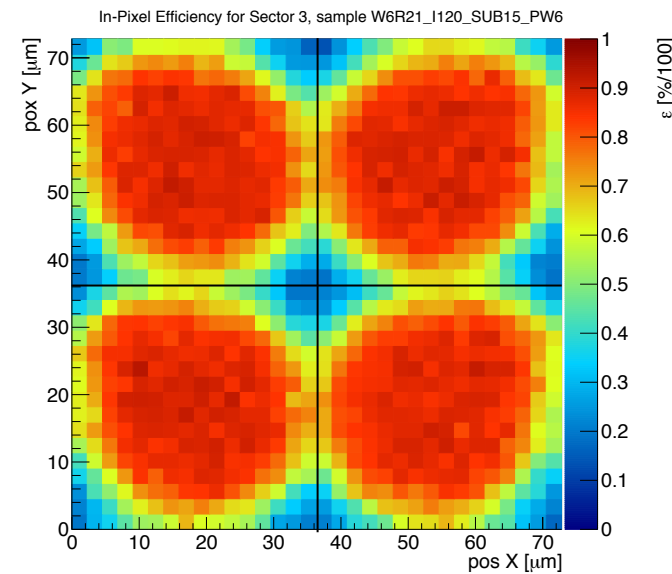
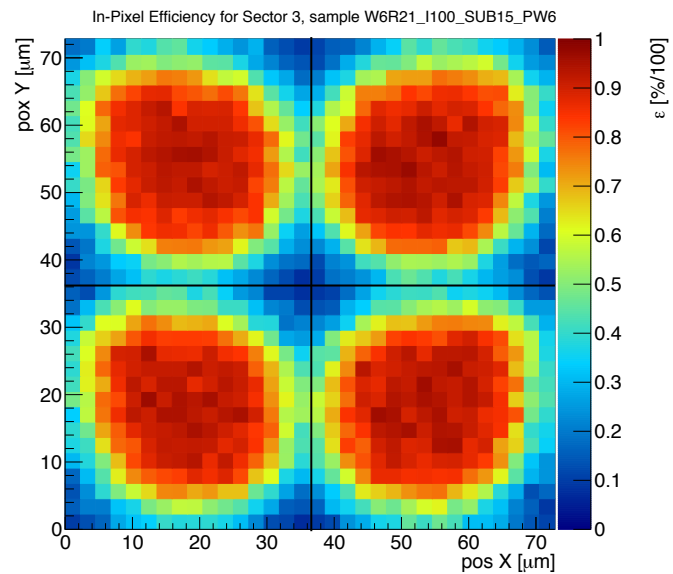
- ♦ In pixel efficiency: overlay of many pixel groups

Unirradiated
(W6R6, S3)



Decreasing threshold, from $\sim 600 e^-$ to $\sim 250(\text{unirr})/350(\text{irr}) e^-$

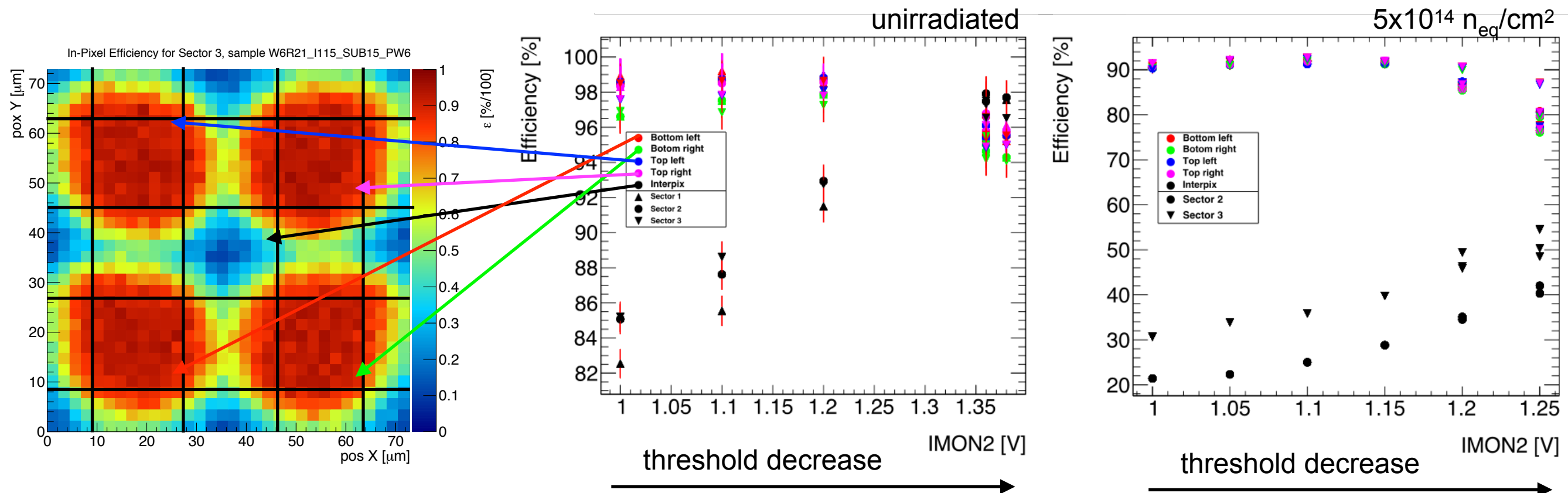
Irradiated
 $5 \times 10^{14} n_{\text{ea}}/\text{cm}^2$
(W6R21, S3)



Couldn't reach
lower threshold

Inefficiency are mainly originating at the corner of the chip

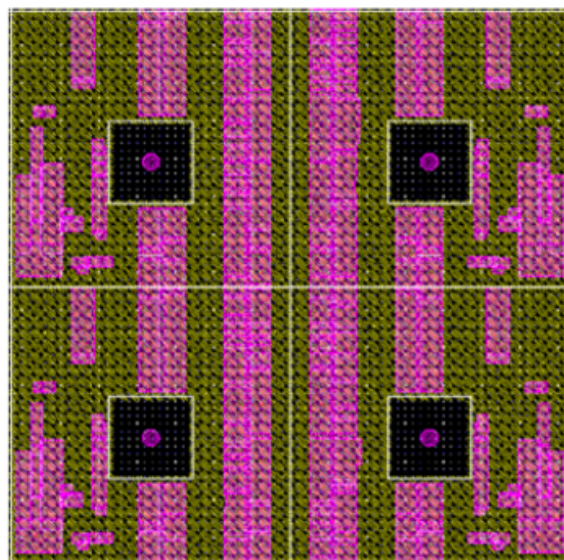
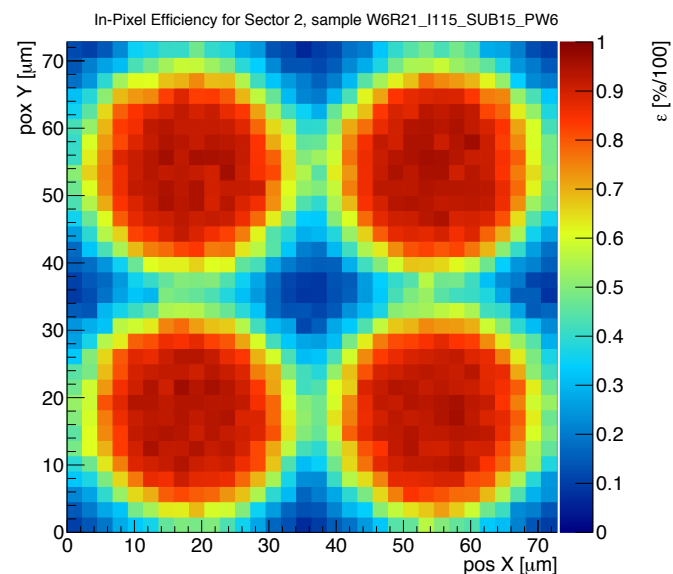
Inefficiency are mainly originating at the corner of the chip



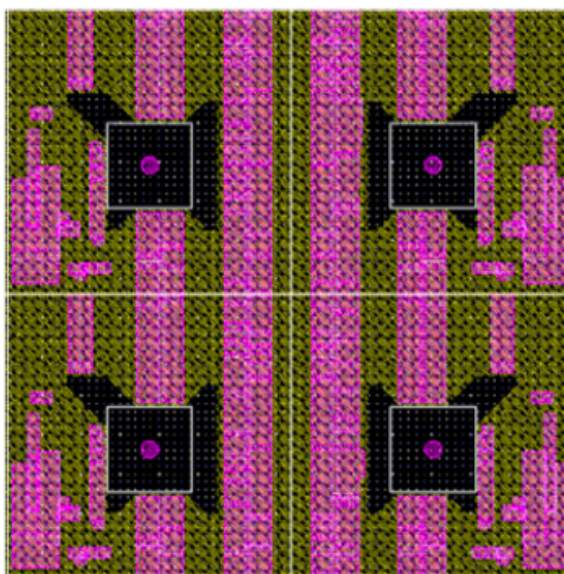
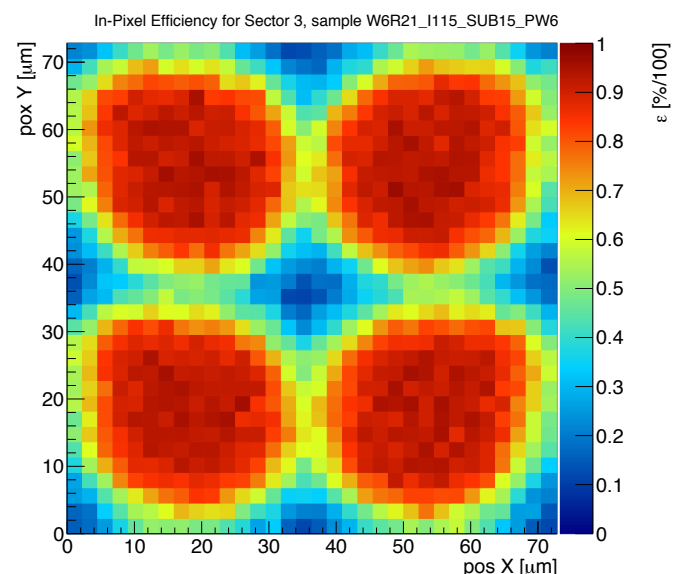
- ◆ Efficiency after irradiation drops more in the corners
- ◆ Center of the pixel is affected by merging at lower thresholds
- ◆ Corners of the pixel improve with lower threshold
- ◆ no strong dependence on substrate voltage in range 6-15 V

Effect of the p-well structures

Sector 2
Max deep
p-well

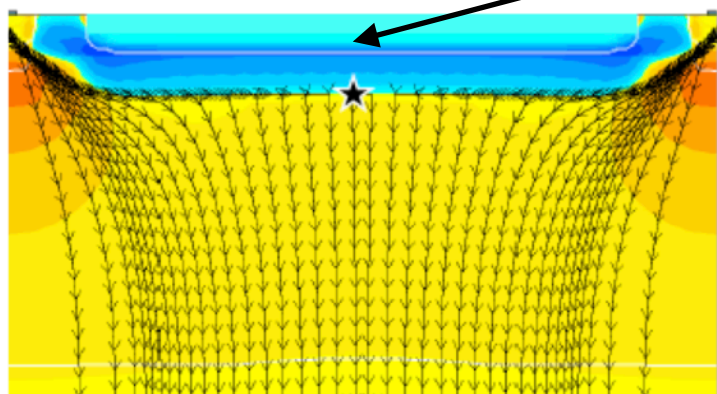


Sector 3
Med deep
p-well

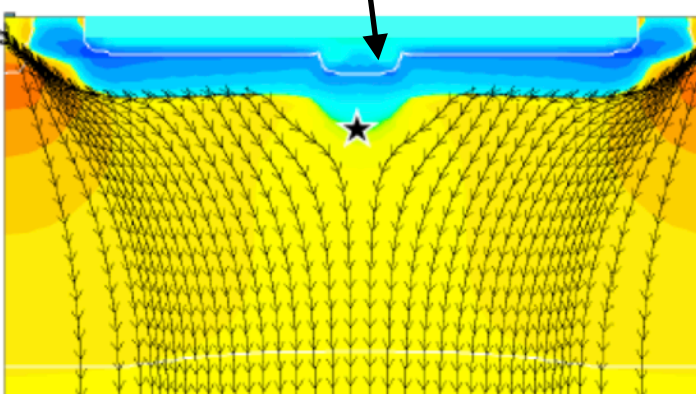


- ◆ Inefficiency structures inside the pixel correlated with **deep PWELL distribution**
- ◆ inspired modifications discussed with the foundry and effort on TCAD simulation
- ◆ proposed modification of the PWELL structure at the chip boundary to water the field configuration

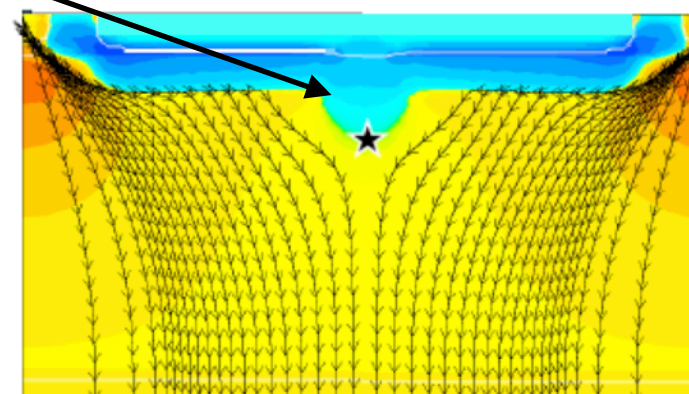
Modified process:



Modified process with additional p-implant:

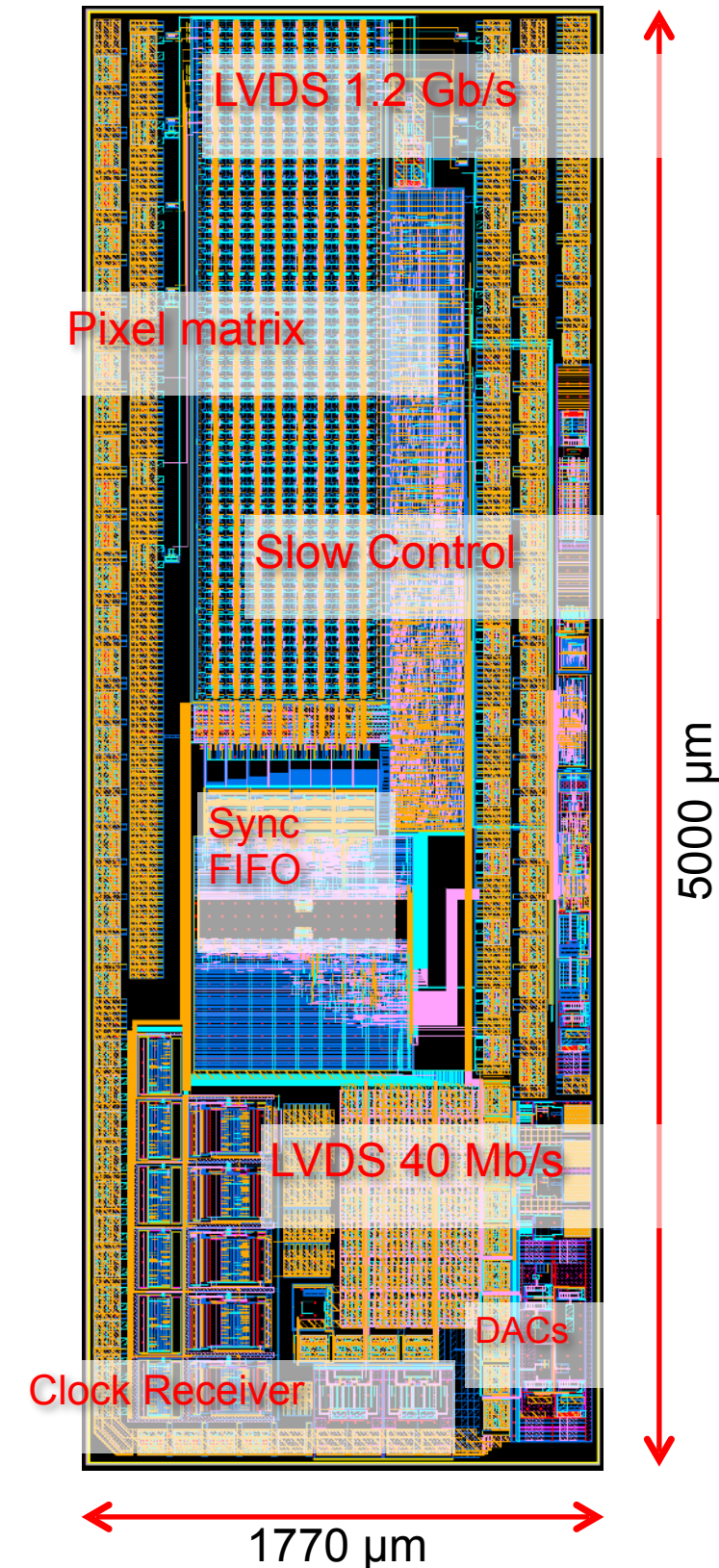
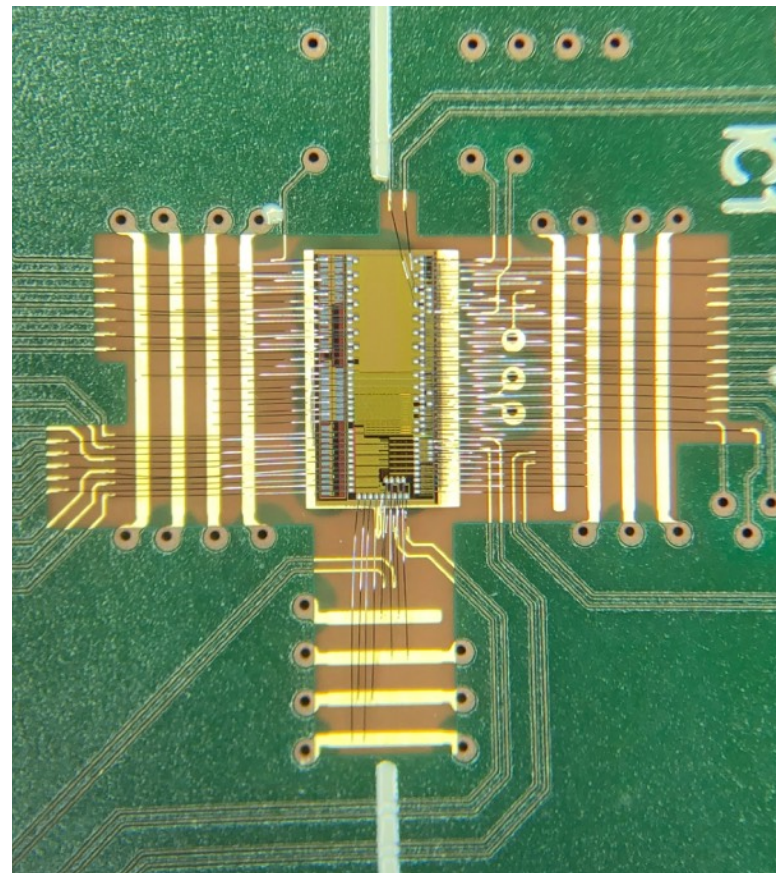


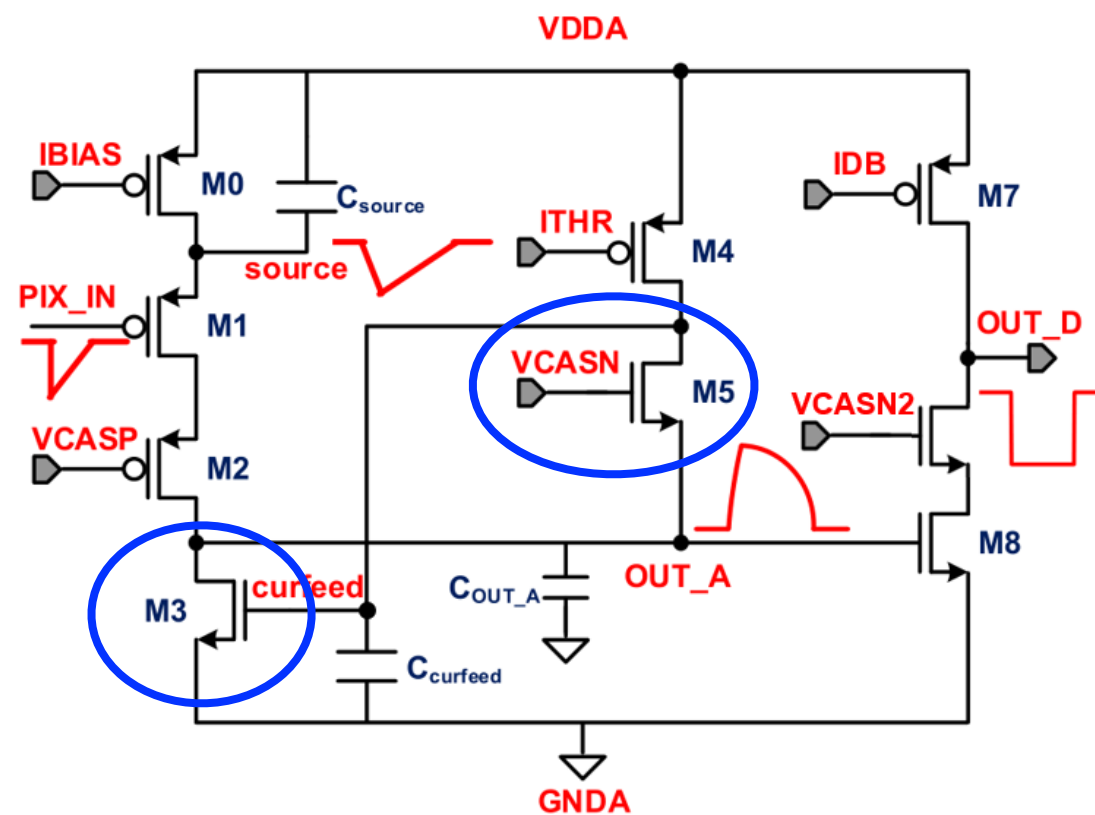
Modified process with gap in n-layer:



- ◆ 5 x 1.7 mm² demonstrator
- ◆ 64 x 16 pixels with 36.4 μm pitch
- ◆ based on the MALTA pixel front-end with key improvements
- ◆ 8 sectors with different analogue front-end design, reset mechanism and sensor implant process
- ◆ different SlowControl implementation
- ◆ periphery data synchronization using a custom RAM memory
- ◆ single serial data stream: 40Mbps or 1.2 Gpbs with 8b10b encoding

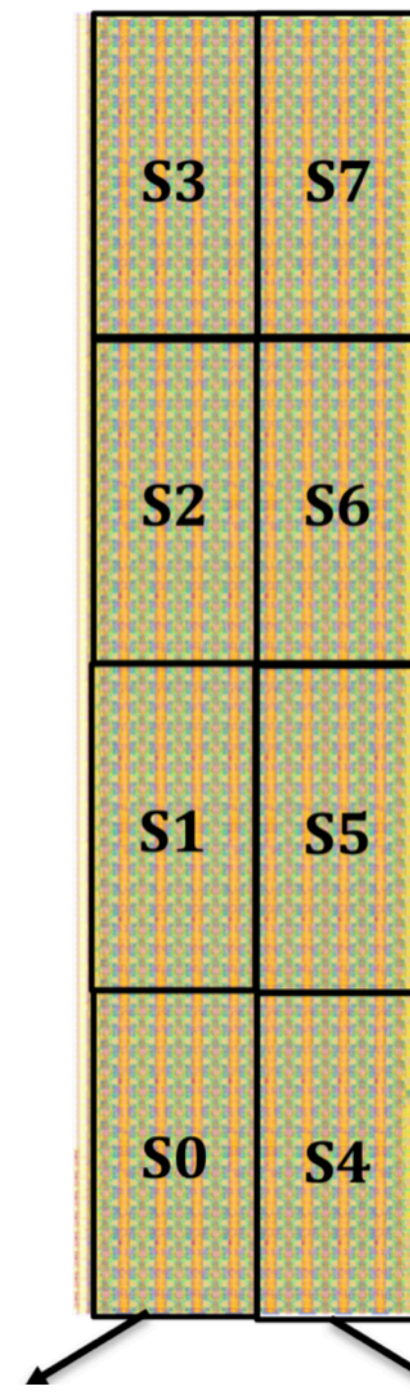
**Mini-MALTA
wire-bonded
on a carrier
board**





◆ Increased size of transistors to reduce RTS noise:

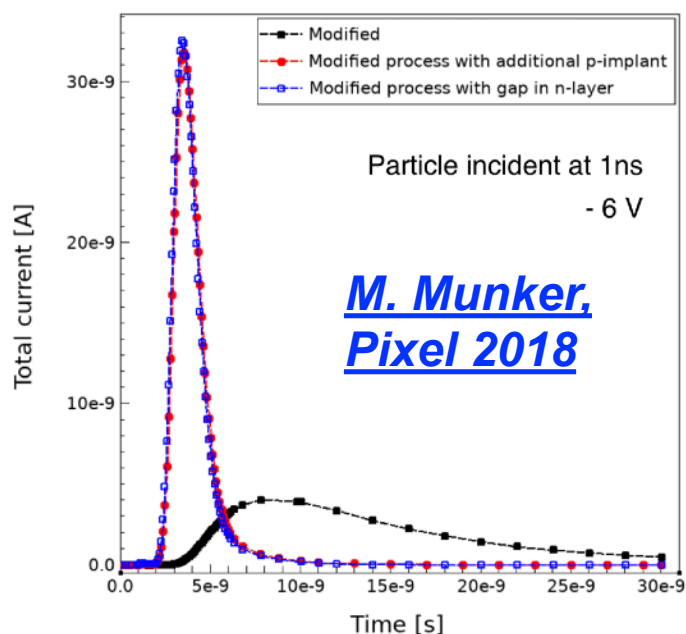
- ◆ M6: x2 larger
- ◆ M3: 20% larger



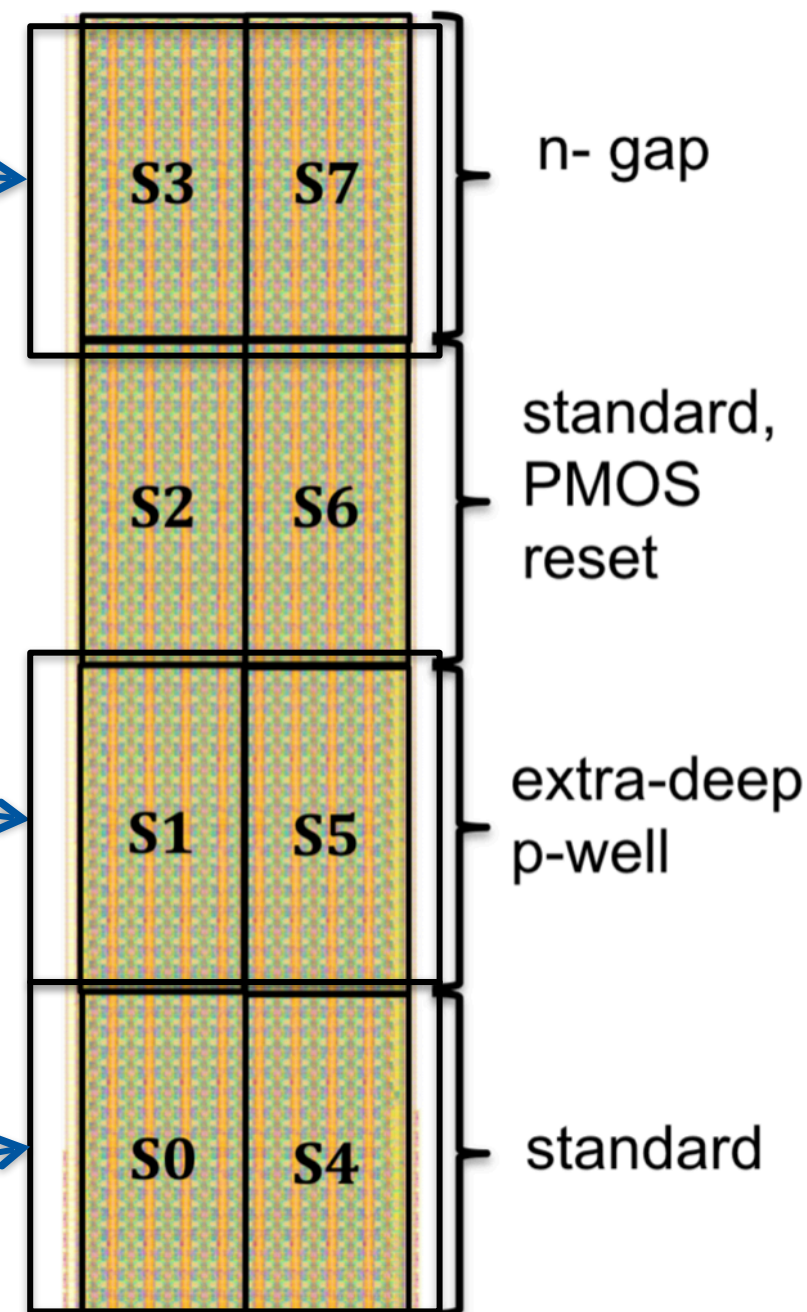
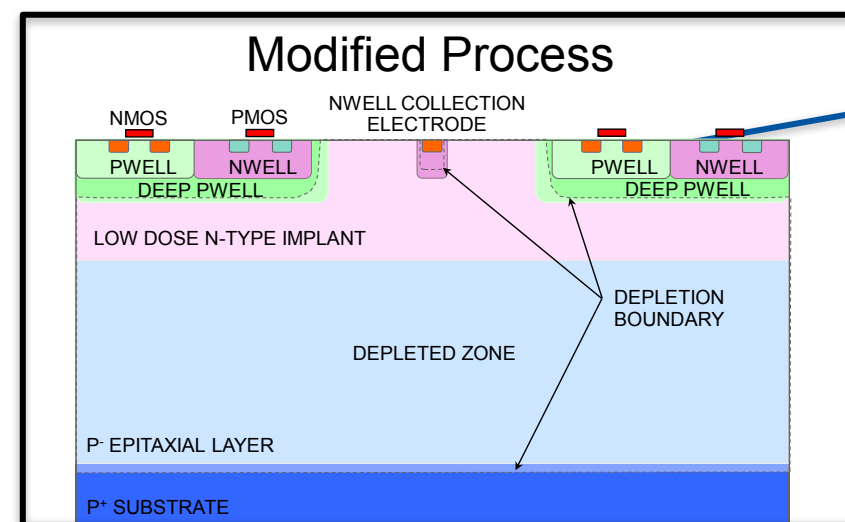
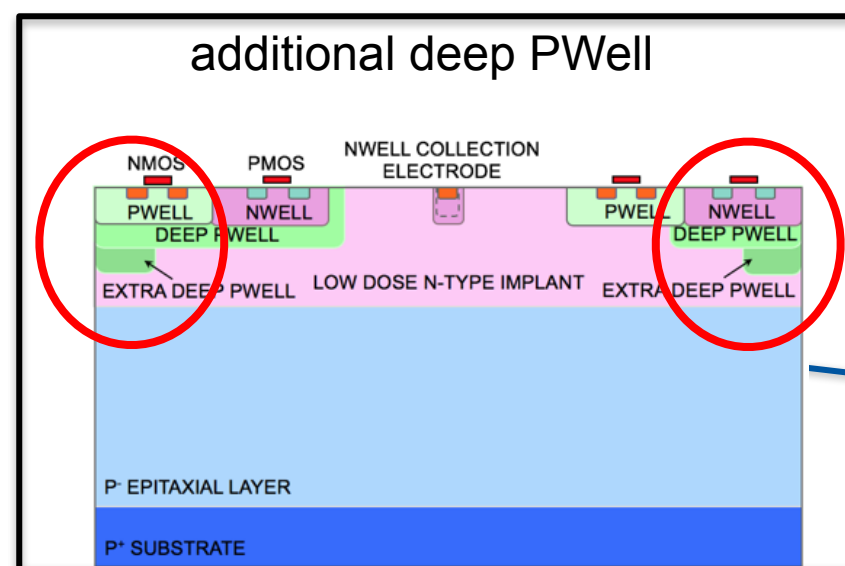
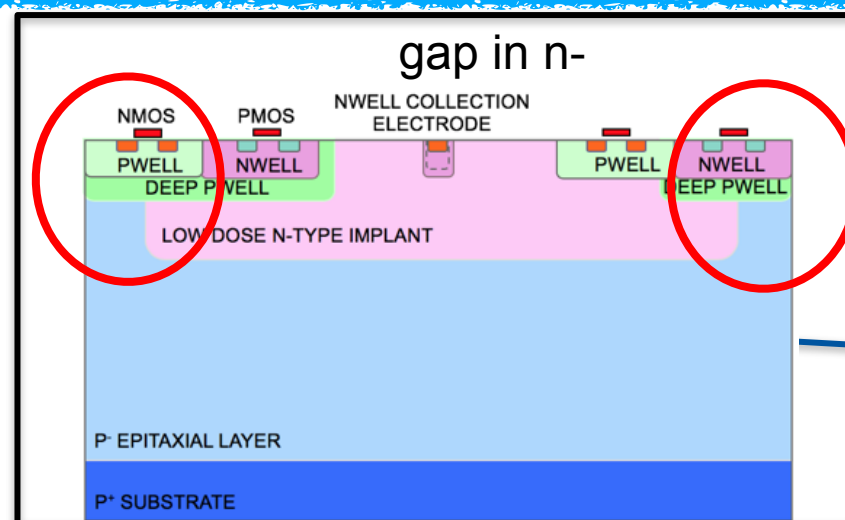
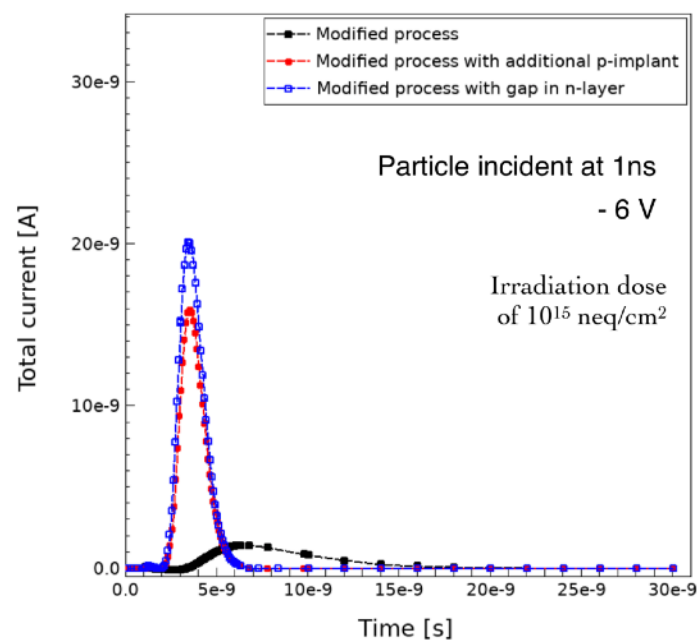
enlarged transistors standard front-end

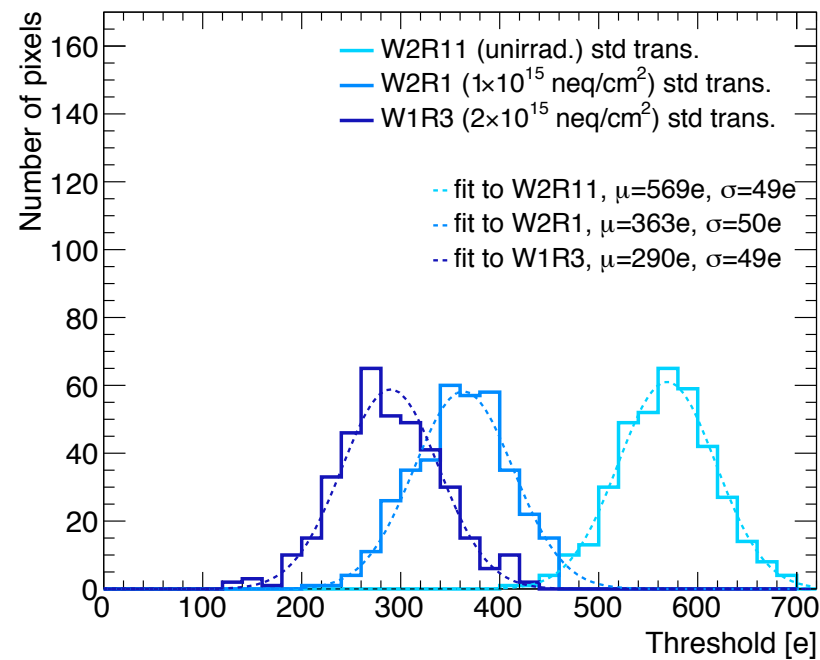
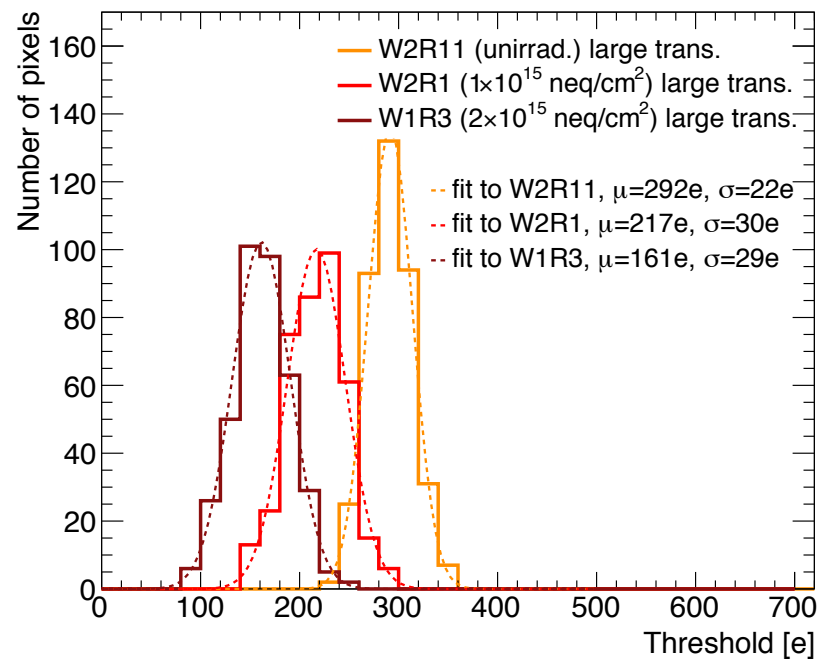
- ◆ Process modification inspired by TCAD simulation

Before irradiation:



After irradiation:

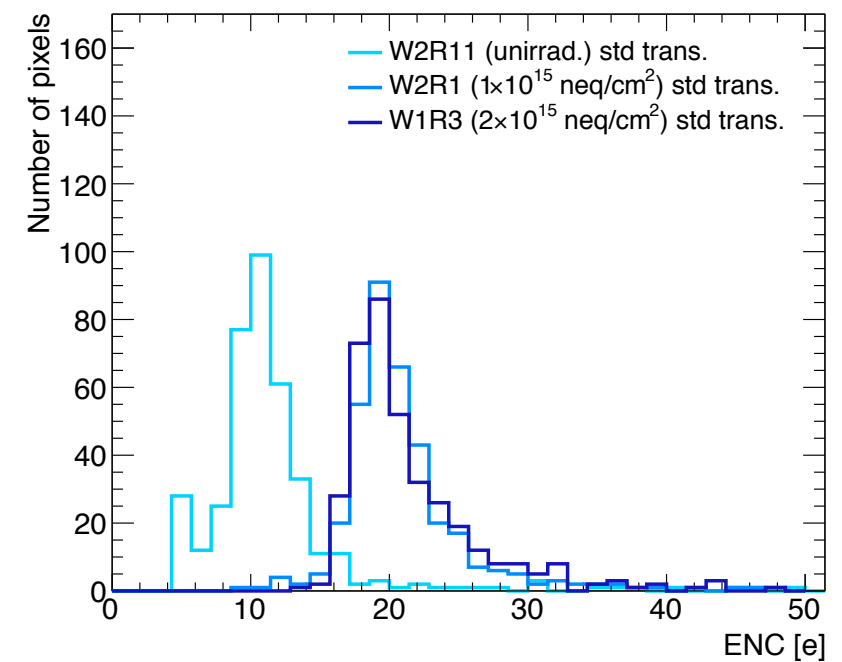
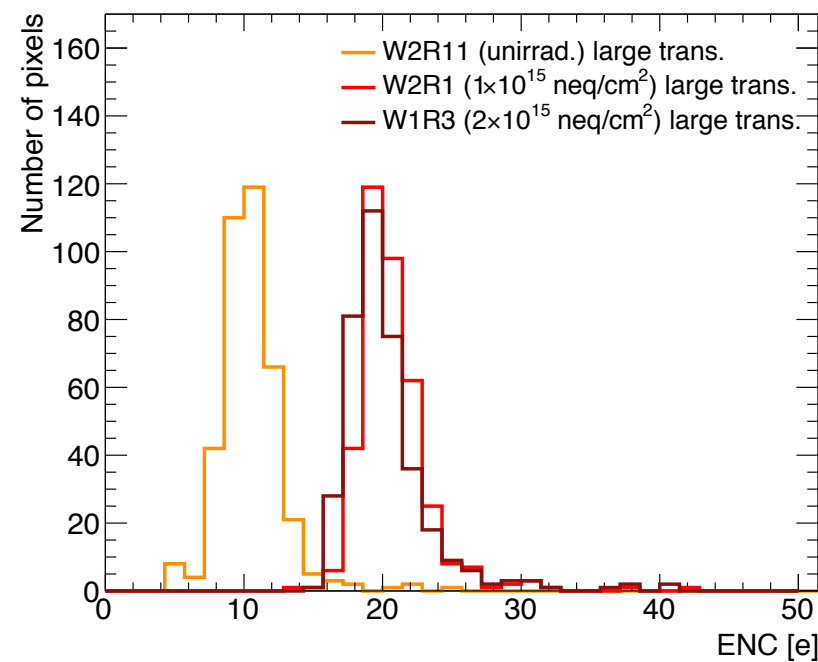




♦ (for the same configuration) enlarged Nmos front end shows **significantly lower threshold and smaller pixel-by-pixel dispection**

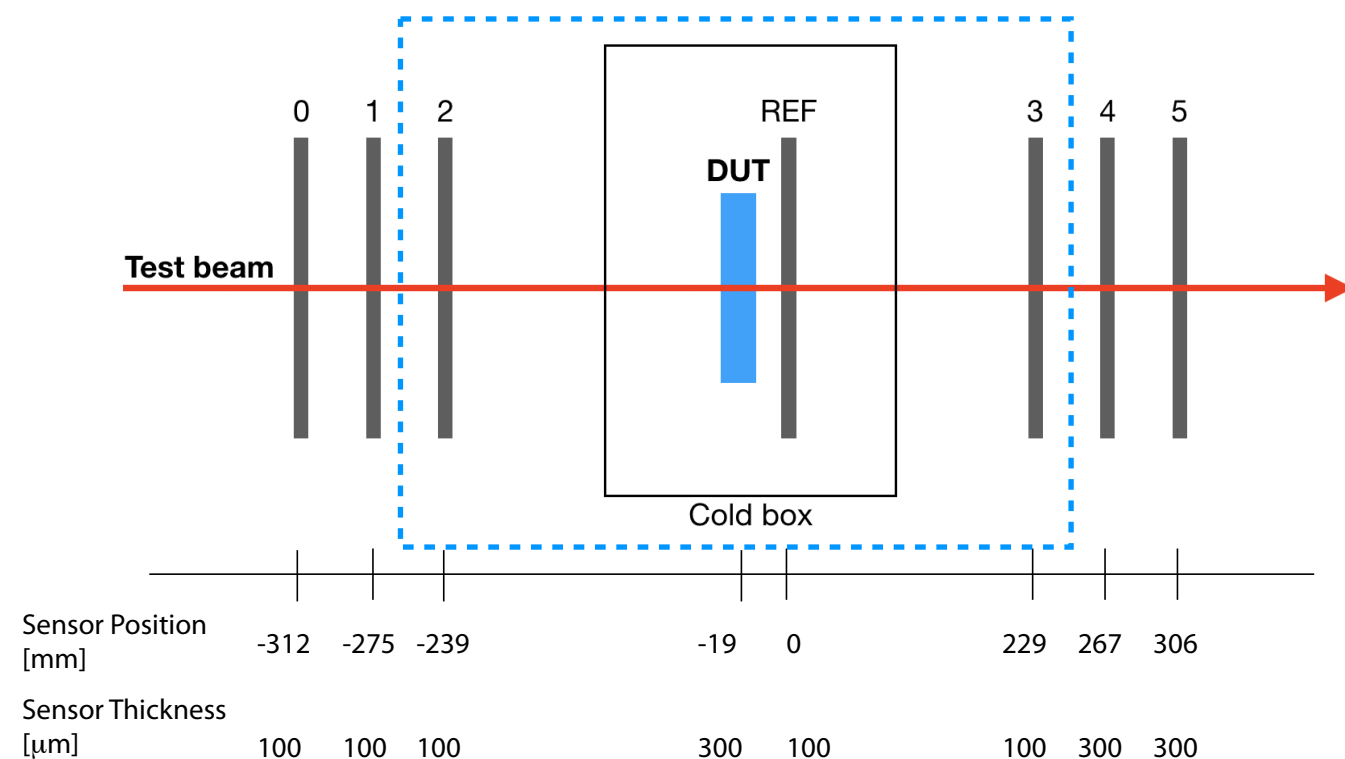
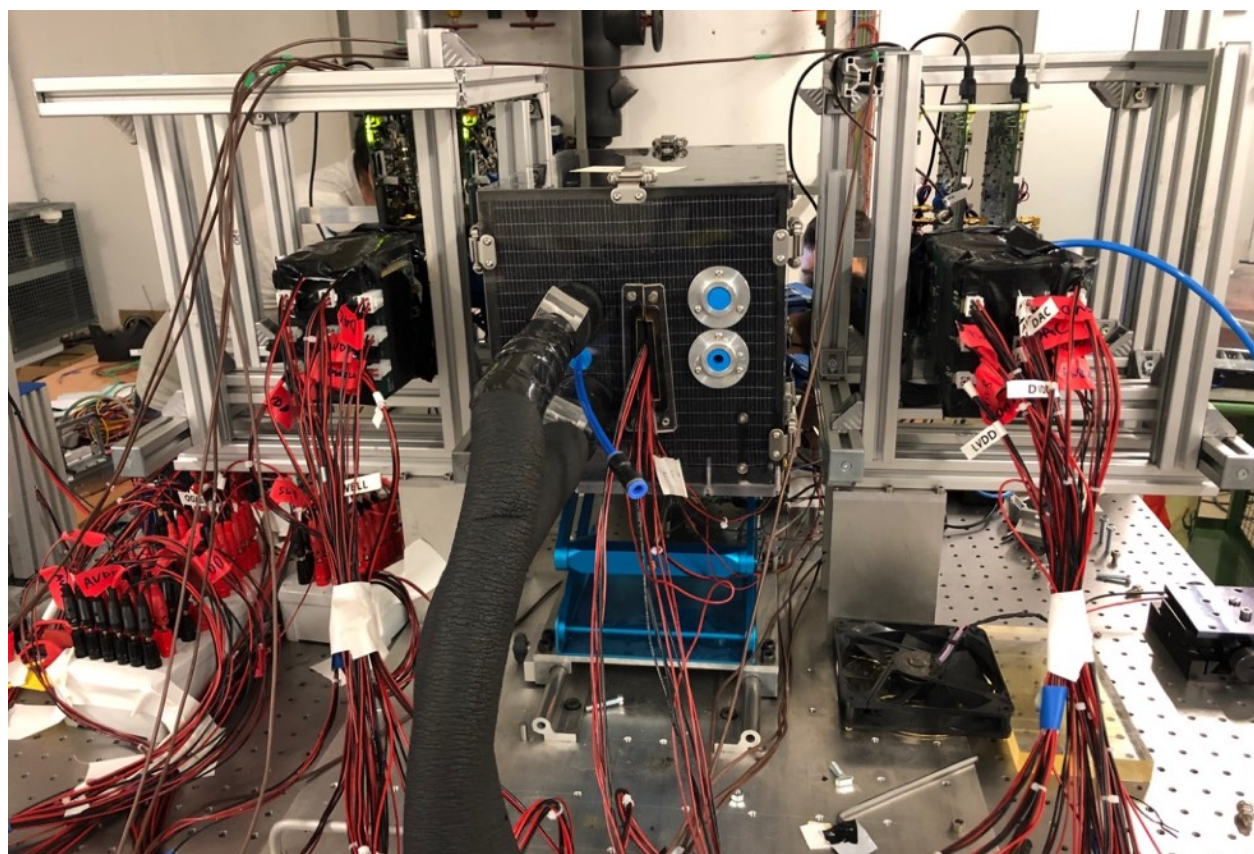
♦ enlarged transistors front end has **smaller average ENC and significantly smaller ENC tails**

♦ noise ~double after irradiation



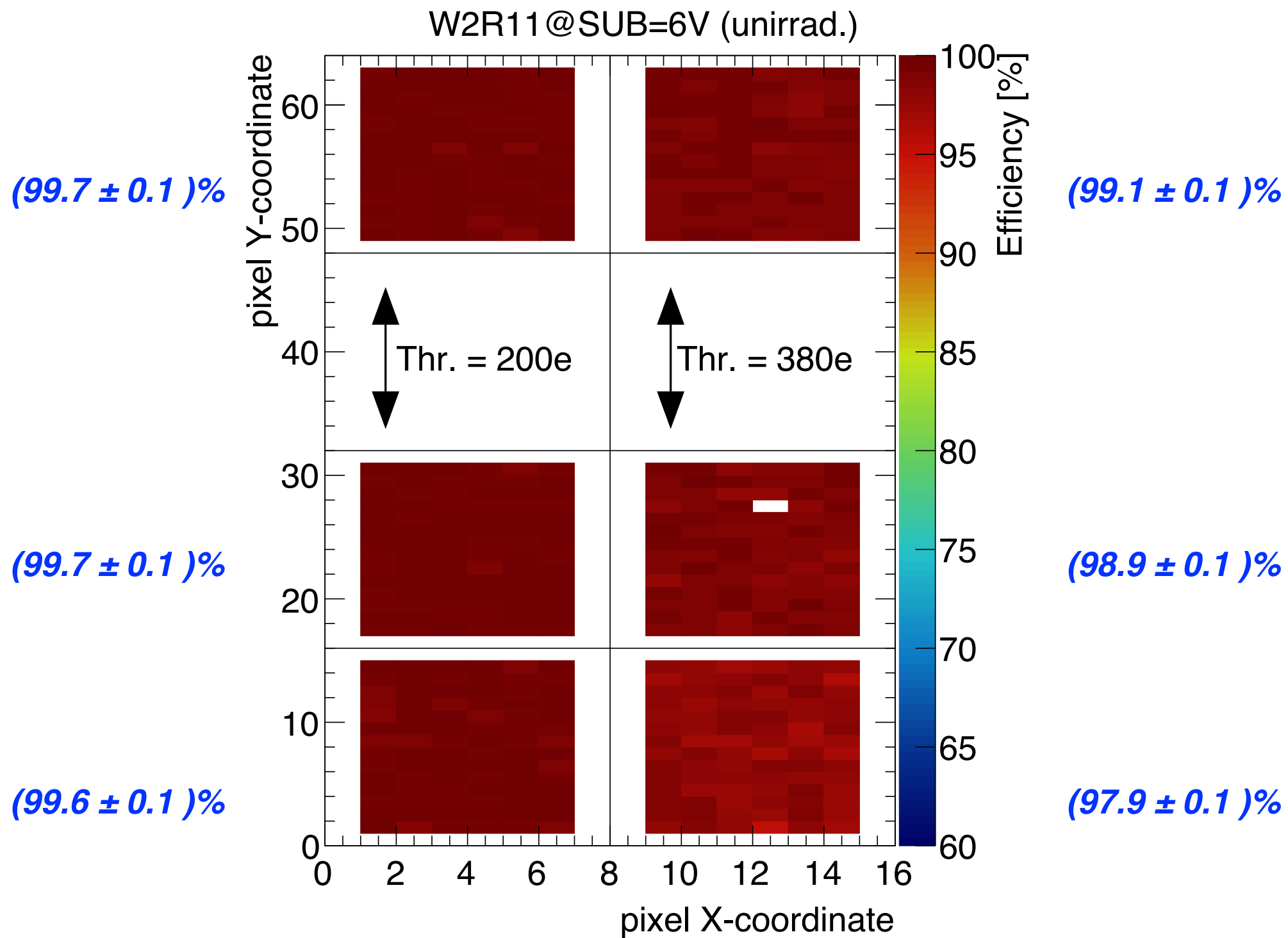
More information on Poster from Lluís Simon Argemi

- ♦ testbeam in ELSA: 2.5 GeV electrons



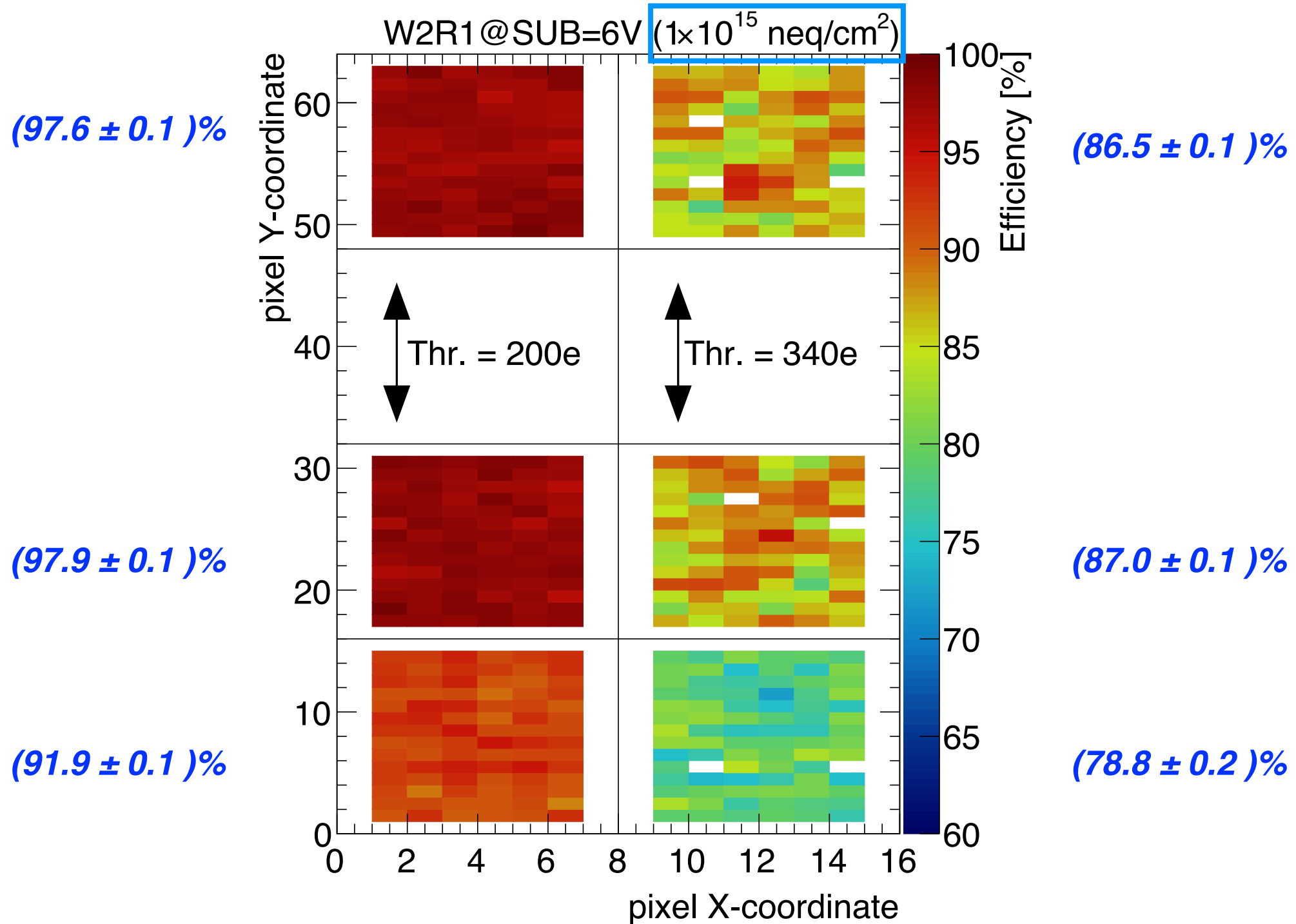
- ♦ new beam telescope made entirely of MALTA(C) planes:
 - ♦ 2 arms (3 planes each) + 1 plane inside the cold box
 - ♦ flexible trigger schema (up to 3 planes coincidence)
 - ♦ precise region of interest capability (also in trigger)
 - ♦ high rate capability [up to few kHz] with low per-event occupancy (~ 1 hit)
 - ♦ **achieving 14 μm track-hit resolution using only 3 tracking planes and General Broken Line (GBL) algorithm in Proteus**
 - ♦ similar performance as MIMOSA telescope in DESY

Efficiency map in Mini-MALTA



- ♦ very high and uniform efficiency before irradiation

Efficiency map in Mini-MALTA

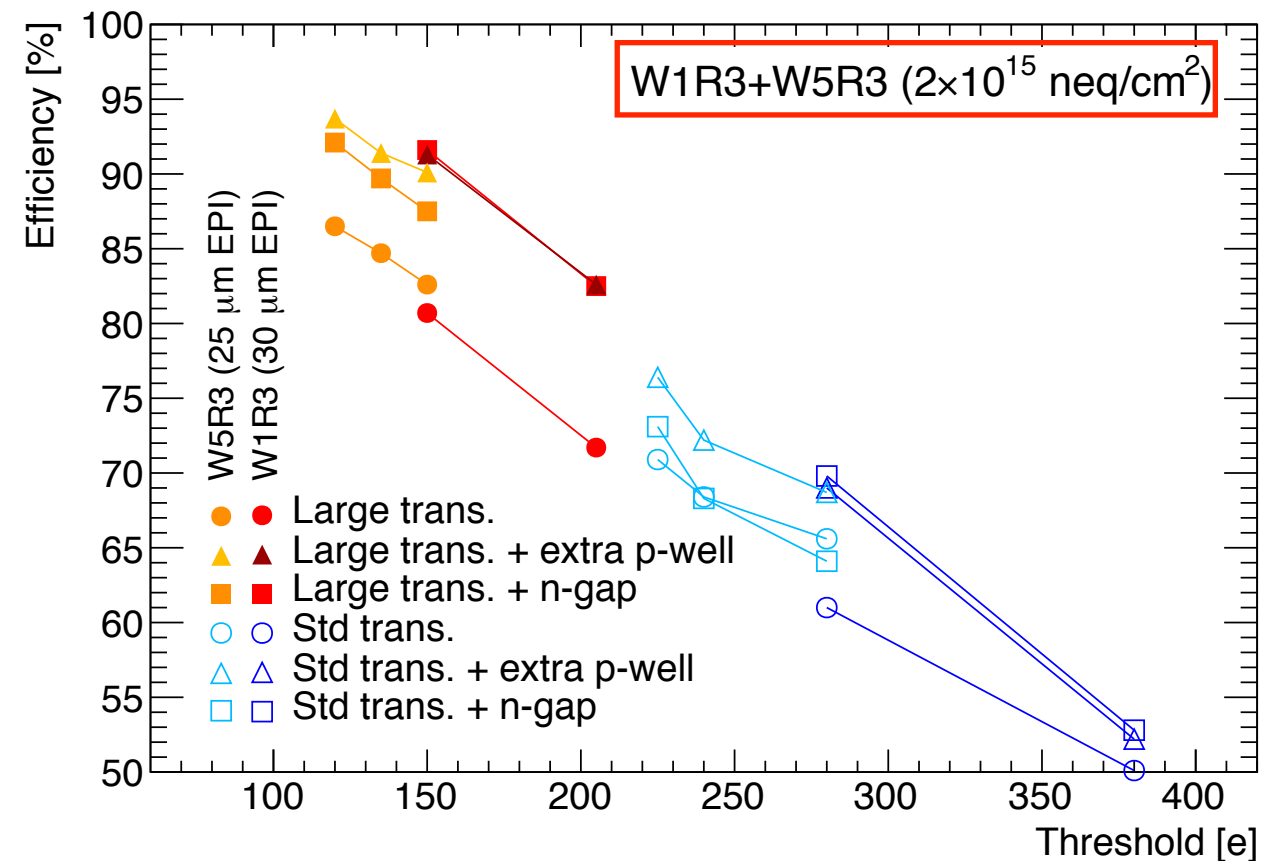
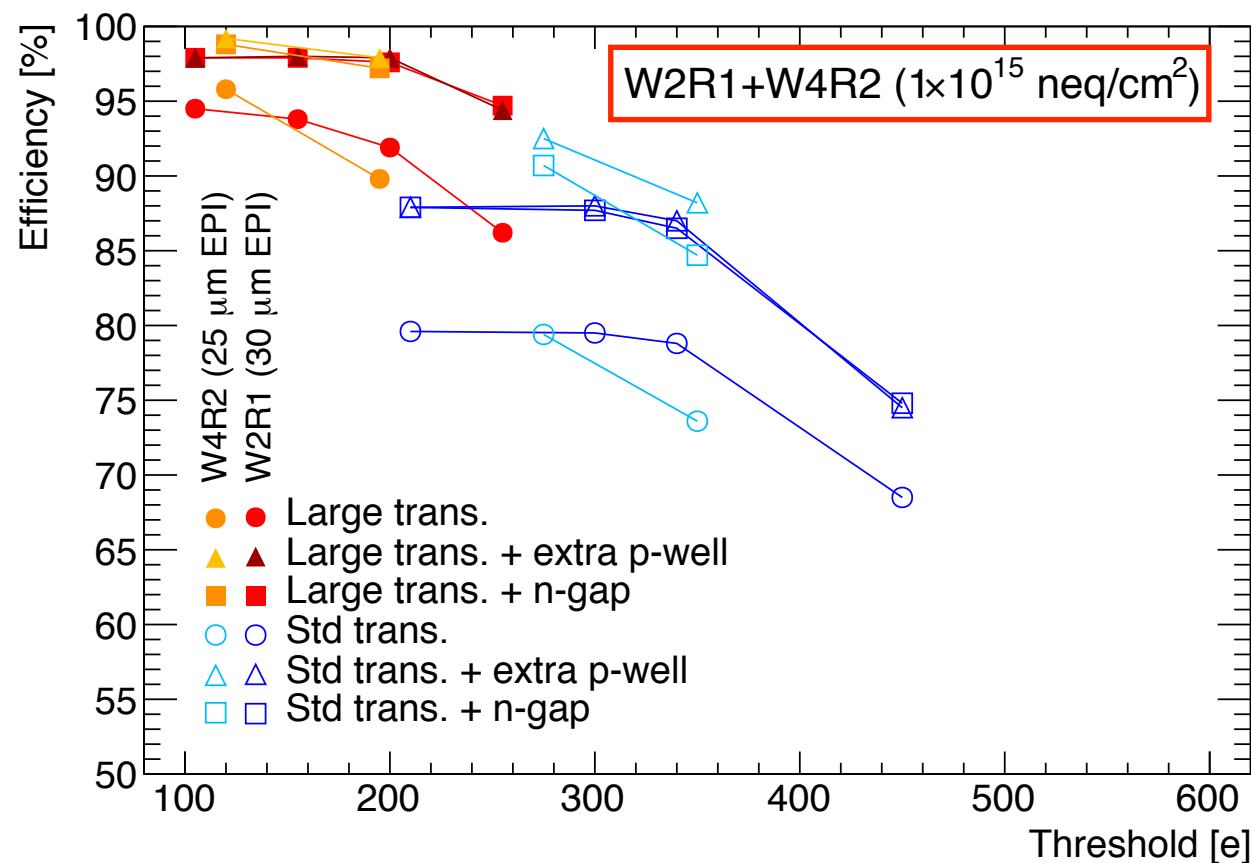


♦ visible improvement in efficiency from modifications:

♦ ~13% improvement due to new transistor

♦ ~6% improvement from process modification: similar improvement from deep p-well and n-gap

Efficiency map in Mini-MALTA: summary



♦ for $1 \text{e}15 \text{ neq/cm}^2$:

♦ efficiency stably above 97% for threshold below 200 el in new sensor modification with enlarged transistors

♦ no strong dependence on substrate voltage in range 6-15 V

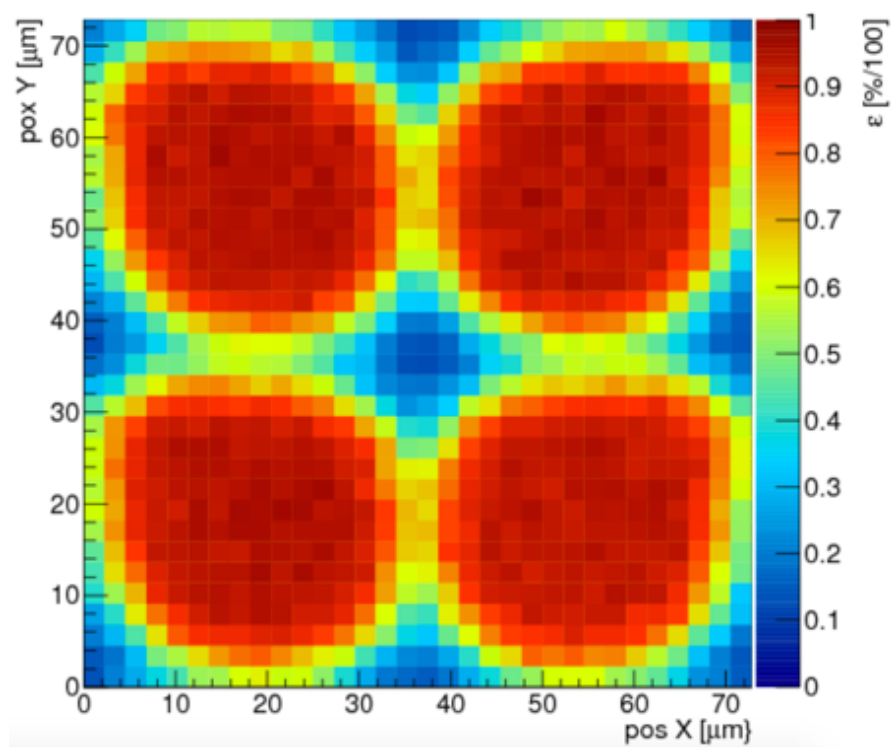
♦ for $2 \text{e}15 \text{ neq/cm}^2$:

♦ monotonic effect of efficiency with threshold

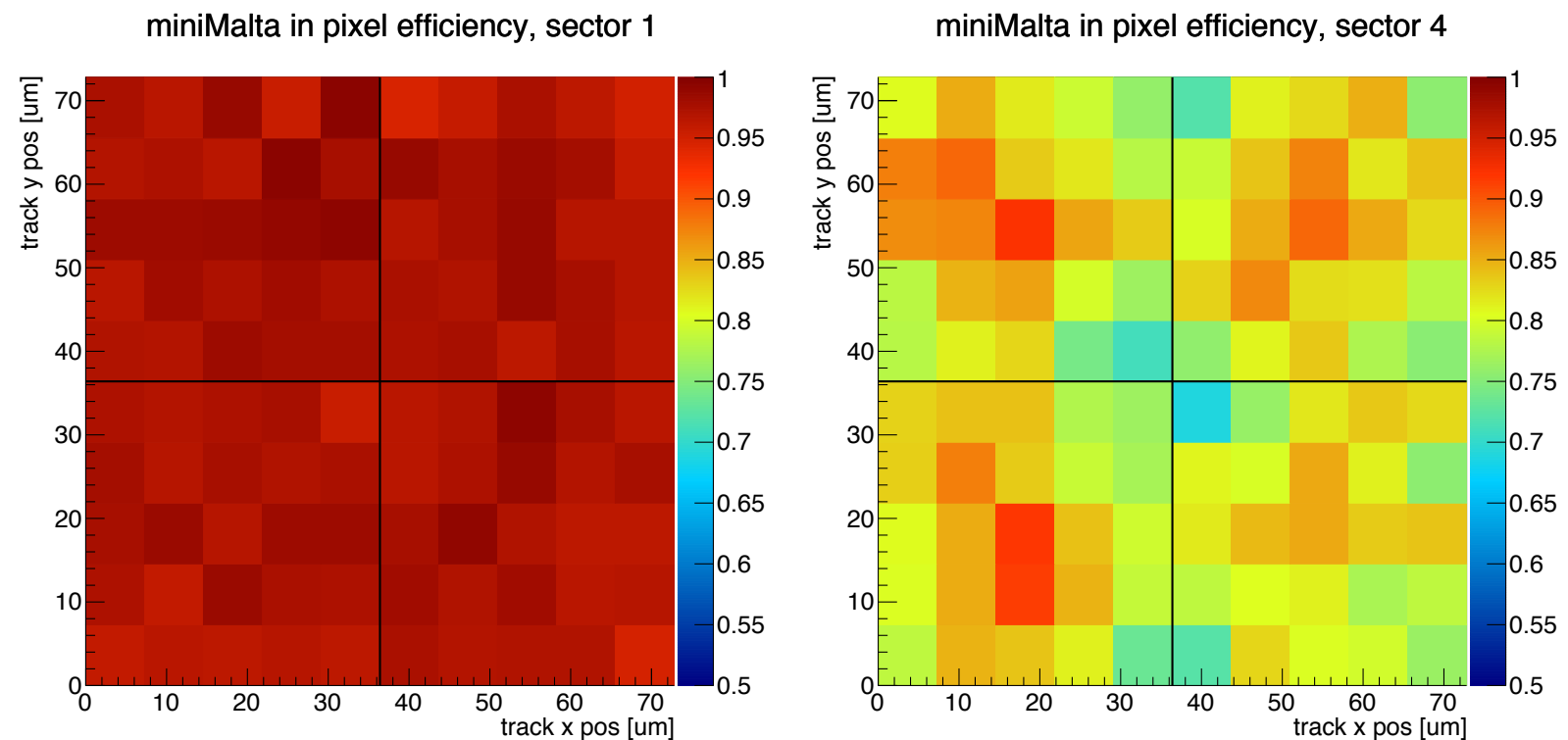
♦ similar improvement pattern across sectors

♦ reaching an efficiency $>90\%$

180 GeV pion beam:
2 μm resolution

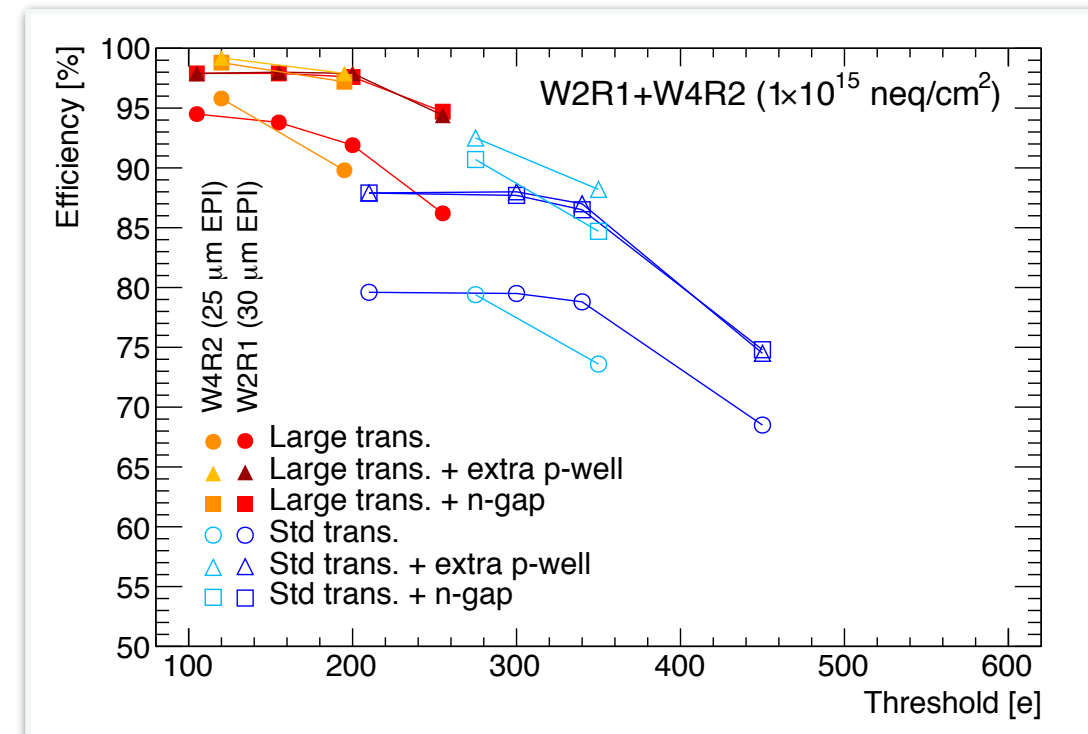


2.5 GeV electron beam: 14 μm resolution



- ♦ ... while waiting for SPS restart ... test beam at Diamond Light Source facility (UK):
 - ♦ 8 keV x-ray beam: close to MIP energy deposition in the chip
 - ♦ scanning position in 1-2 μm steps (corresponding to externally measured beam spot size)
 - ♦ ... publication coming soon ...

- ♦ Mini-MALTA is a prototype designed to improve rad. hardness of the MALTA chip:
 - ♦ modification of the sensors and improved transistors in the front end lead to **>97% efficiency after $1e15$ n_{eq}/cm^2**
 - ♦ publication under preparation



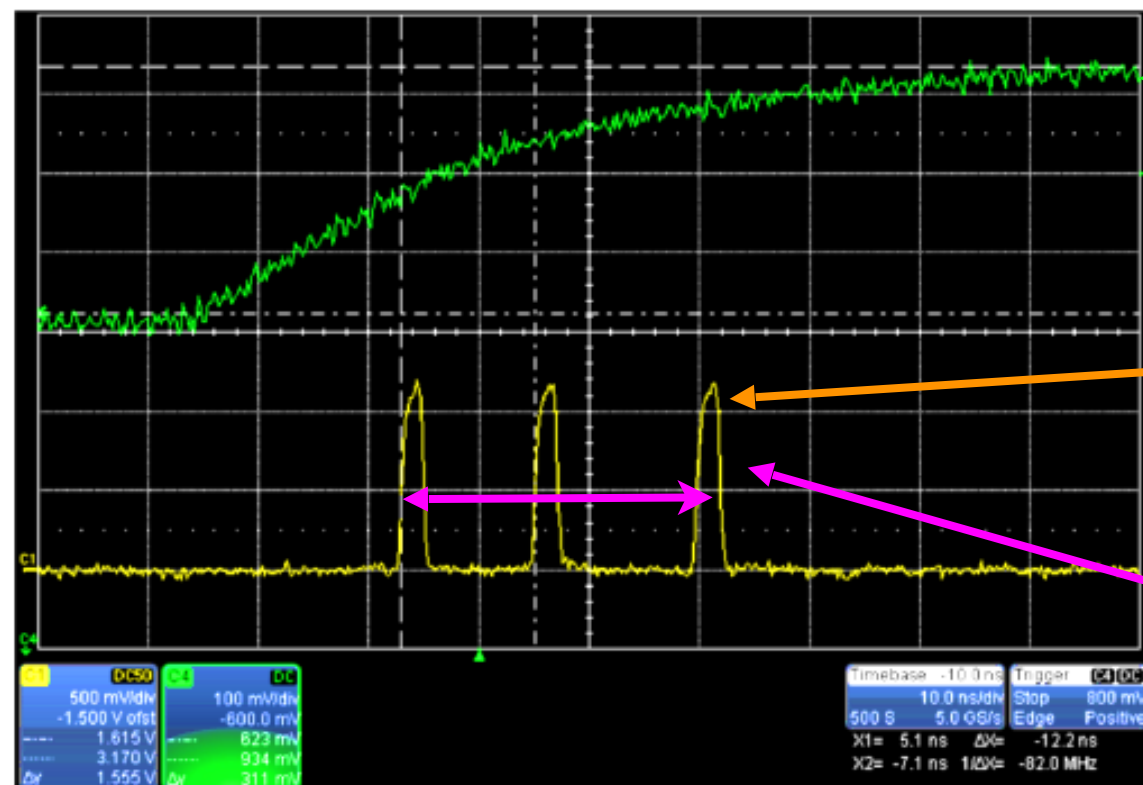
- ♦ looking ahead (full size chips):

- ♦ **Fourth submission:** chip delivered and assembled, testing started yesterday(!)
 - ♦ same slow control implementation as MaltaC
 - ♦ different substrate type for the wafer. **From TJ standard to Czochralski type**
 - ♦ should increase the size of the depletion region (more signal)
- ♦ Single Event Upset testing campaign in November
- ♦ submission of new chip in December 2019
 - ♦ half size MALTA with improved front-end transistors
 - ♦ MonoPix_V2: including 3 bits for pixel threshold tuning

- The measurements leading to these results have been performed at the TestBeam Facility at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF).
- Measurements leading to these results have been performed at the E3 beam-line at the electron accelerator ELSA operated by the university of Bonn in Nordrhein-Westfalen, Germany.
- This project has received funding from the European Union's Horizon 2020 Research and Innovation programme under Grant Agreement no. 654168.(IJS, Ljubljana, Slovenia)
- Dr. Ben Phoenix, Prof. David Parker and the operators at the MC40 cyclotron in Birmingham (UK).
- Proteus: "Kiehn, Moritz et al., Proteus beam telescope reconstruction, doi:10.5281/zenodo.2579153"

BackUp

Asynchronous readout

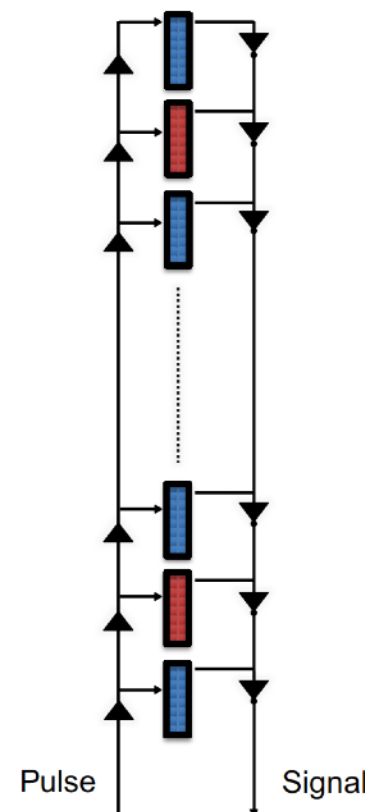


analog output of one of the pulsed pixels

Reference signals (asynchronous 2 ns pulse for each hit) pulsing pixels at top, bottom and middle of a column

Measured delay between first two pulses 12.2 ns

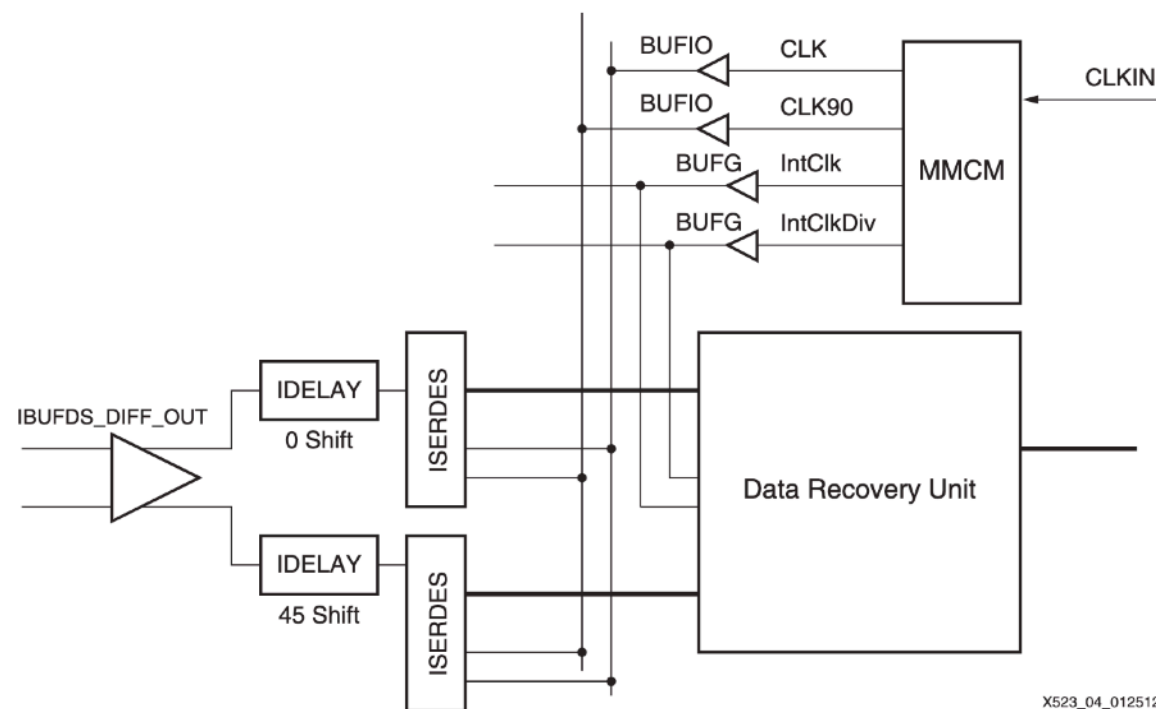
- Propagation delay of asynchronous signals through double column bus up to 8 ns



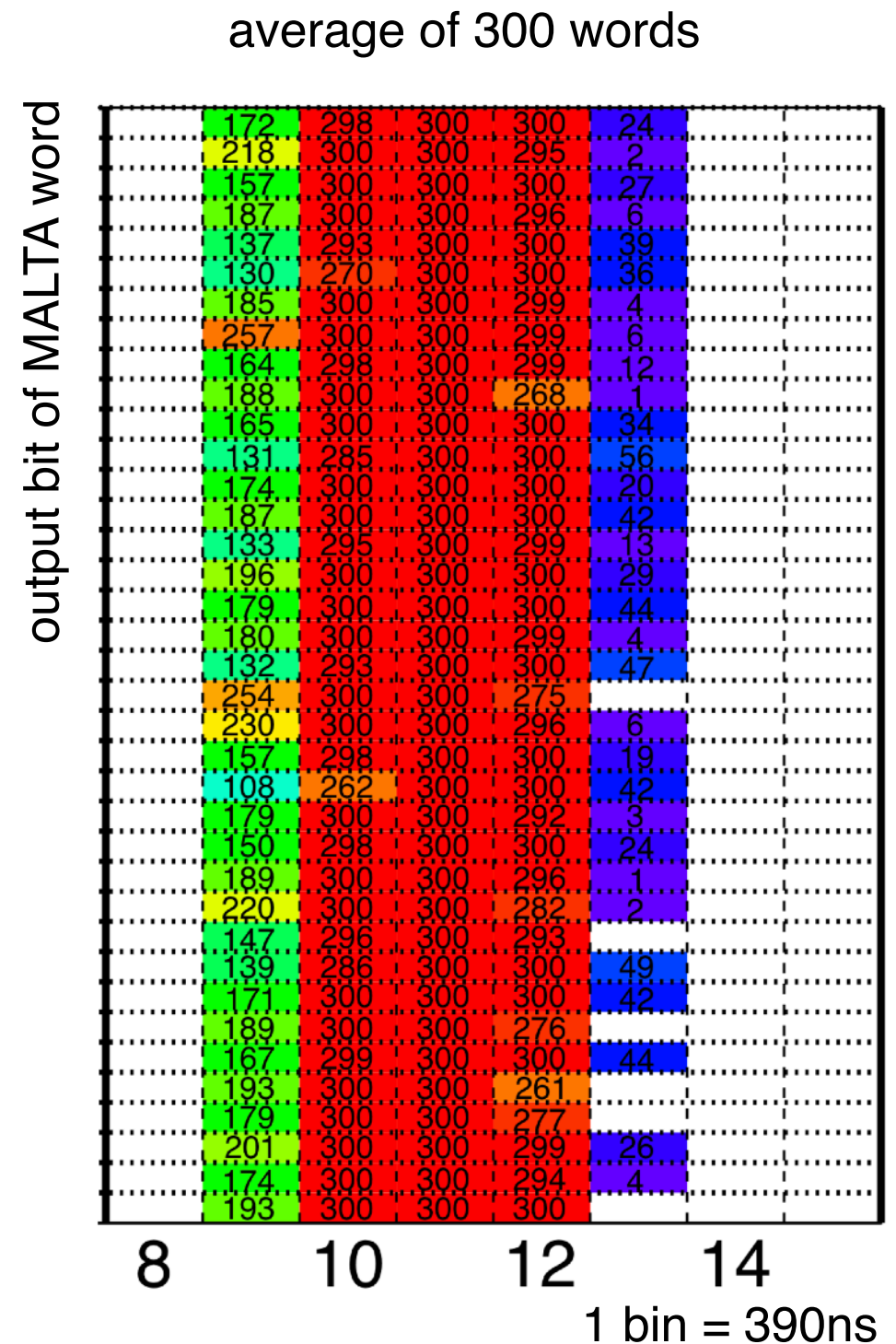
P-well bias	Simulation	2 groups [ps]	Column [ns]
0V	Pulse delay	460	14.75
	Signal delay	225	7.20
-0.5V	Pulse delay	478	15.29
	Signal delay	234	7.48
-1V	Pulse delay	490	15.68
	Signal delay	241	7.71
-1.5V	Pulse delay	503	16.10
	Signal delay	246	7.87
-1.8V	Pulse delay	511	16.35
	Signal delay	249	7.70

- Total delay for half a column = pulse delay / 2 + signal delay / 2 = **12 ns** (-1.8 V p-well bias)

- Read-out on Xilinx 7-series VC707
- Implemented asynchronous oversampling of the data
 - 2 copies of the data (0,45)
 - 2 clock buffers (0,90)
 - 2 samplings per clock (0,180)
 - 8 samples per signal
 - 320 MHz clock domain
 - 4 GHz effective sampling
 - 3 to 4 samples per pulse

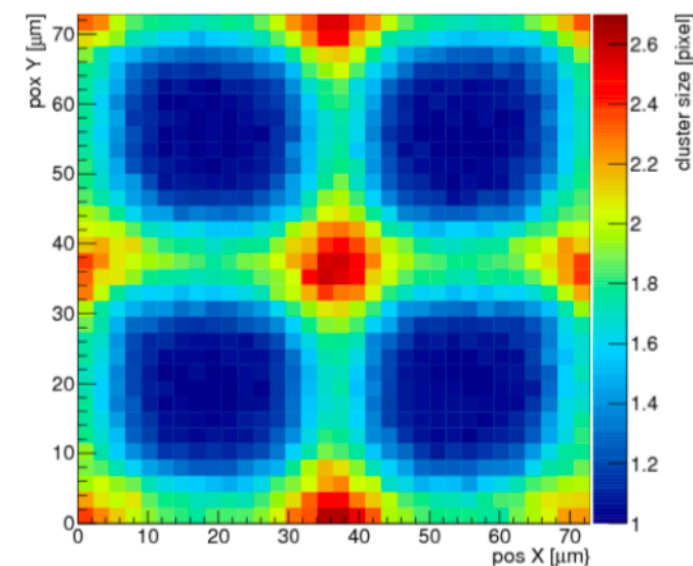
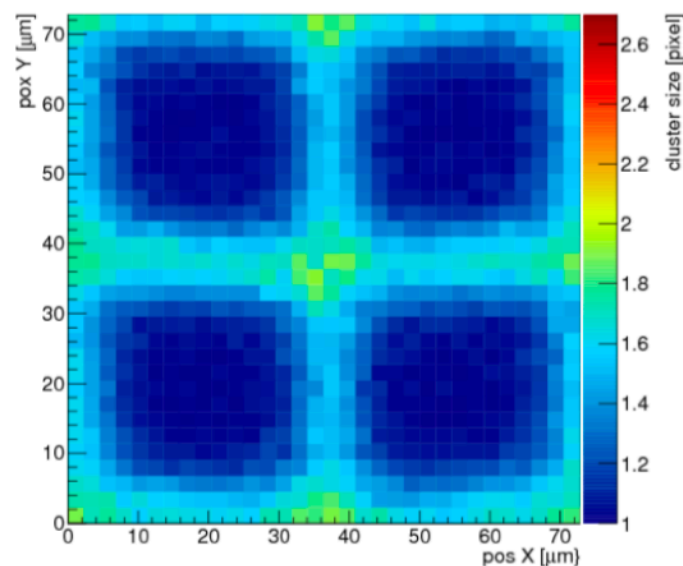
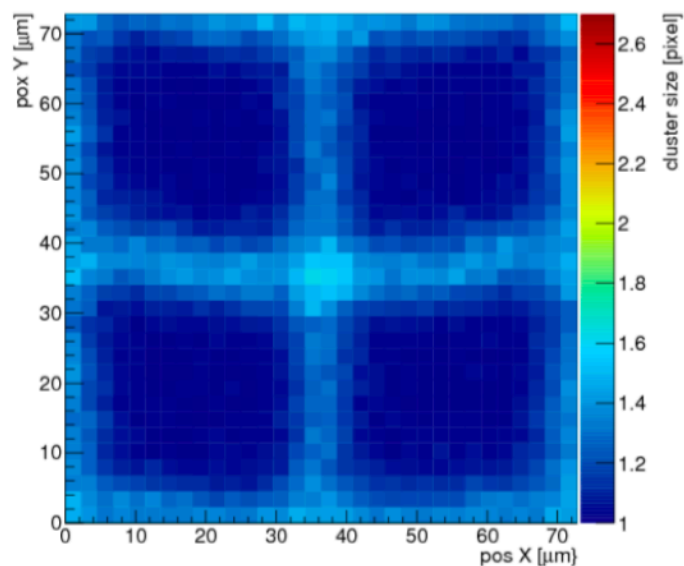


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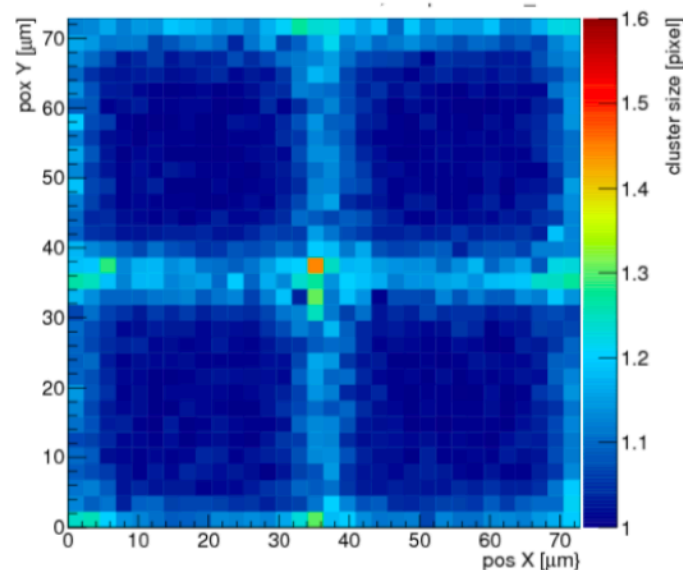
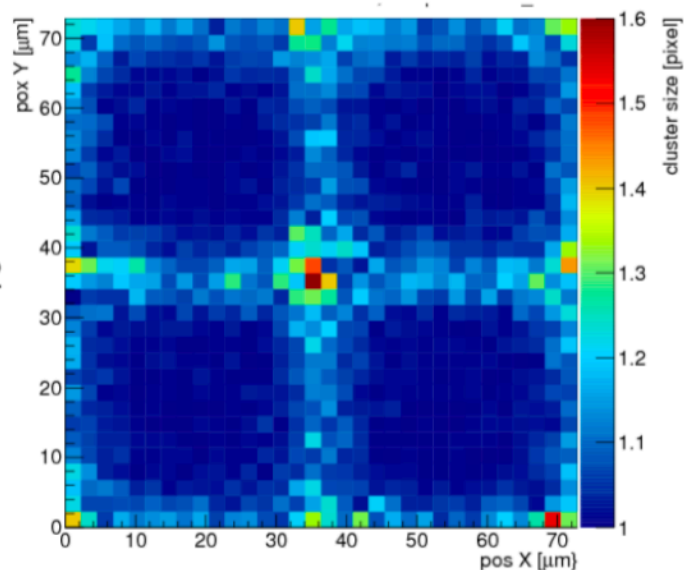
Cluster size plots

Unirradiated
(W6R6, S4)



Decreasing threshold, from $\sim 600 e^-$ to $\sim 250(\text{unirr})/350(\text{irr}) e^-$

Irradiated
 $5 \times 10^{14} n_{\text{eq}}/\text{cm}^2$
(W6R21, S4)



Couldn't reach
lower threshold

Efficiency: versus sub start voltage

